## MAINTENANCE MANUAL

ERICSSON 🗾 🛞

## MULTISITE COORDINATOR II 4-CHANNEL AUDIO BOARD 19D903302P1, REVISION E&M

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## SPECIFICATIONS

TEMPERATURE

DIMENSIONS (Height X Width)

WEIGHT

**POWER** 

#### **RELAY OUTPUTS:**

120 Volts AC or DC At 0.2 Amperes 30 Volts 30 VA

**DIGITAL LEVELS** 

DIGITAL DATA RATE

**AUDIO LEVELS** 

#### **AUDIO DISTORTION**

#### AUDIO HUM AND NOISE

 $-30^{\circ}$ C to  $+60^{\circ}$ C

200 mm X 330 mm (typical)

1.0 kG (typical)

+ 5.0 Volts  $\pm 10\%$ 1.75 Amperes (maximum) 2.0 Amperes Fuse + 15 Volts  $\pm 10\%$ 0.3 Amperes (maximum) 0.5 Amperes Fuse - 15 Volts  $\pm 10\%$ 0.3 Amperes (maximum) 0.5 Amperes Fuse

Maximum Switching Voltage Maximum Switching Current Maximum Carry Current Maximum Switching Power

TTL/CMOS/HCMOS RS-232C RS-485 FUTUREBUS OPTOCOUPLER

9600 BAUD 1 MEGA BAUD 2.048 MEGA BAUD

+ 12 dBm (maximum) - 25 dBm (minimum)

Less Than 2.5%

Less Than 50 dB

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## **TABLE 1 - J1 PIN DEFINITIONS**

CONNECTOR	SIGNAL	A(AUDIO)	LEVEL
PIN	NAME	D(DIGITAĹ)	TYPE
J1-32A	GND	•	0 VOLTS
J1-1B	CL (4)	D	FUTUREBUS
J1-2B	GND	-	O VOLTS
J1-3B	CL (5)	D	FUTUREBUS
J1-4B	GND	-	0 VOLTS
J1-5B	CL (6)	D	FUTUREBUS
I1-6B	GND		O VOLTS
I1-7B	CL(7)	Л	FUTURERUS
I1-8B	GND	-	O VOLTS
11-9B	TDM BUS (0)	л	FUTUPERUS
11-10B	GND	D .	A VOLTS
I1-11B	TDM BUS (1)		
I1-12B	GND	D	A VOLTS
11-13B	TDM BUS (2)	י ת	
$I_{1-1AB}$	$\frac{10M}{CND}$	D	FUTUREBUS
1 - 15P	TDM BUS (2)	- D	O VOLIS
	IDM BUS (3)	D	FUTUREBUS
J1-10D		-	O VOLTS
JI-I/B	IDM BUS (4)	D	FUTUREBUS
J1-18B	GND	-	O VOLTS
J1-19B	TDM BUS (5)	D	FUTUREBUS
J1-20B	GND	-	O VOLTS
J1-21B	TDM BUS (6)	D	FUTUREBUS
J1-22B	GND	-	O VOLTS
J1-23B	TDM BUS (7)	D	FUTURE
J1-24B	GND	-	O VOLTS
JI-IC	+ 5	-	+ 5 VOLTS
J1-2C	GND	-	O VOLTS
J1-3C	GND	-	O VOLTS
J1-8C	AUX SER +	D	RS-485
J1-9C	AUX SER -	D	RS-485
J1-12C	GND	-	0 VOLTS
J1-13C	DB (0)	D	TTL
J1-14C	DB (1)	D	TTL
J1-15C	DB (2)	D	TTL
J1-16C	DB (3)	D	TTL
J1-17C	DB (4)	D	TTL
J1-18C	DB (5)	D	TTL
J1-19C	DB (6)	D	TTL
J1-20C	DB (7)	D	TTL
J1-22C	GND	-	0 VOLTS
J1-23C	ENBL (0)	D	TTL
J1-24C	ENBL (1)	D	TTL
J1-25C	ENBL (2)	D	TTL
J1-26C	ENBL (3)	D	TTL
J1-27C	ENBL (4)	D	TTL
J1-28C	ENBL (5)	D	TTL
J1-29C	ENBL (6)	D	TTL
J1-30C	ENBL (7)	D	TTL
J1-31C	+ 5 `´	-	+5 VOLTS
J1-32C	GND	-	0 VOLTS

## **TABLE 3 - TEST POINT DEFINITIONS**

.

TEST POINT	TEST POINT		
NUMBER	NAME		
TP1	CODEC CO 3 (NU)		
TP2	CODEC VFXI 3		
TP3	CODEC VFXO 3 (NU)		
TP4	STATION 2175 BURST CHANNEL 3		
TP5	OP AMP DRIVING CHANNEL 3 OUT		
TP6	CODEC CO 2 (NU)		
TP7	CODEC VFXI 2		
TP8	CODEC VFXO 2 (NU)		
TP9	STATION 2175 BURST CHANNEL 2		
TP10	OP AMP DRIVING CHANNEL 2 OUT		
TP11	CODEC CO 1 (NU)		
TP12	CODEC VFXI 1		
TP13	CODEC VFXO 1 (NU)		
TP14	STATION 2175 BURST CHANNEL 1		
TP15	OP AMP DRIVING CHANNEL 1 OUT		
TP16	CODEC VFXO 4 (NU)		
TP17	CODEC VFXI 4		
TP18	CODEC CO 4 (NU)		
TP19	OP AMP DRIVING CHANNEL 4 OUT		
TP20	STATION 2175 BURST CHANNEL 4		
TP21	GND		
TP22	-12V		
TP23	+ 12V		
TP24	-5V		
TP25	+ 5V		
TP26	2175		
TP27	BIT CLK		
TP28	SSYNC		
TP29	FSYNC		
TP30	TDMX BUS 0		
TP31	TDMX BUS 1		
TP32	TDMX BUS 2		
TP33	TDMX BUS 3		
TP34	TDMX BUS 4		
TP35	TDMX BUS 5		
TP36	TDMX BUS 6		
TP37	TDMX BUS 7		
TP38	LCA PROGRAM CHANNEL 4		
TP39	SINOUT TO CHANNEL 4		
TP40	CODEC SERIAL DATA OUT 4	CODEC SERIAL DATA OUT 4	
TP41	LCA PROGRAM CHANNEL 3		
TP42	SINOUT TO CHANNEL 3	SINOUT TO CHANNEL 3	
TP43	CODEC SERIAL DATA OUT 3	CODEC SERIAL DATA OUT 3	
1P44	LCA PROGRAM CHANNEL 2	LCA PROGRAM CHANNEL 2	
TP45	SINOUT TO CHANNEL 2	SINOUT TO CHANNEL 2	
	CODEC SERIAL DATA OUT 2	CODEC SERIAL DATA OUT 2	
	LCA PROGRAM CHANNEL 1		
	SINOUT TO CHANNEL 1		
11749	GODEC SEKIAL DATA OUT 1		
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## **TABLE 3 - TEST POINT DEFINITIONS**

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TEST POINT NUMBER	TEST POINT NAME		
		$\neg$	
	CODEC CO 3 (NU)		
	CODEC VEXO 3 (NUI)		
	CODEC VERO 3 (NU)		
	STATION 2175 BURST CHANNEL 3		
	OP AMP DRIVING CHANNEL 3 OUT		
	CODEC CO Z (NU)		
	CODEC VIXO 2 (NU)		
	STATION 2175 BURST CHANNEL 2		
	OP AMP DRIVING CHANNEL 2 OUT		
TD19			
IP12	CODEC VEXT I		
	CODEC VFXO I (NU)		
	STATION 2175 BURST CHANNEL 1		
	OP AMP DRIVING CHANNEL 1 OUT		
IPI6	CODEC VFXO 4 (NU)		
1P17	CODEC VFXI 4		
1118	CODEC CO 4 (NU)		
1119	OP AMP DRIVING CHANNEL 4 OUT		
	STATION 2175 BURST CHANNEL 4		
1P21	GND		
122	-12V		
1 P23	+ 12V		
1P24	-5V		
1P25	+5V		
1P26	2175		
	BITCLK		
1 P28	SSYNC		
1 P29	FSYNC		
1P31	TDMX BUS 1		
1P32	TDMX BUS 2		
1P33	TDMX BUS 3		
	TDMX BUS 4		
	IDMX BUS 5		
	IDMX BUS 6		
	IDMX BUS /		
1P38	LCA PROGRAM CHANNEL 4		
1P39	SINOUT TO CHANNEL 4		
	CODEC SERIAL DATA OUT 4	CODEC SERIAL DATA OUT 4	
1P41	LCA PROGRAM CHANNEL 3	LUA PROGRAM UHANNEL 3 SINOUT TO CHANNEL 2	
	SINOUT TO CHANNEL 3	SINOUT TO CHANNEL 3	
	CODEC SERIAL DATA OUT 3	CODEC SERIAL DATA OUT 3	
	LCA PROGRAM CHANNEL 2	LCA PROGRAM CHANNEL 2	
TP45	SINOUT TO CHANNEL 2	SINOUT TO CHANNEL 2	
	CODEC SERIAL DATA OUT 2	CODEC SERIAL DATA OUT 2	
	LUA PROGRAM CHANNEL 1	LCA PROGRAM CHANNEL 1	
1 ľ 4ð TD40	SINUUT TO CHANNEL I	SINOUT TO CHANNEL 1	
1 [ 1 [ 1 ]			

LED	LED DEFINITION	
CR1	+ 5 VOLTS	
CR2	+ 12 VOLTS	
CR3	- 12 VOLTS	
CR4	- 5 VOLTS	
LED 1	FSYNC	
LED 2	SSYNC	
LED 3	BIT CLK	
LED 4	2175	
CR5	CHANNEL ADDRESS WRITE	
CR6	CPU RUN	

TABLE 4 - LED DEFINITIONS

## DESCRIPTION

Ericsson GE's 4-Channel Audio Board (19D903302G1) is used in the MultiSite Coordinator II switching system and consists of four (4) identical bidirectional audio processing and routing circuits, and a control circuit. Each audio circuit (audio channel section) converts incoming analog audio signals from trunked repeater sites or console(s) into digitized audio signals. These digitized audio signals are then outputted to a **TDM** audio network (refer to Figure 1). The audio channel circuitry also takes selected digitized audio signals from the **TDM** audio network and converts them from digital to analog form. The resulting analog signals are sent to RF repeater sites or consoles "channels" for transmission.

The TDM audio network is a Timed-Division-Multiplexed (TDM) bus. The TDM bus provides multiple time-shared channels for routing digitized audio signals between nodes.

#### - NOTE

Since there are four identical audio circuits (channels), the circuitry for only one audio channel (channel 3) is shown in Figure 2 - Audio Circuit Block Diagram and referred to in the following Circuit Analysis.

The control section of the Audio Board provides control and clock signals to the audio channel sections. The control section also provides an interface to the module controller board(s). This interface between the module controller board(s) allows the active controller board to communicate with the control registers and other control circuits of the Audio Board control section. The functions of the module controller board and the Audio Board control section are designed to be overlapping and redundant.

During times when the module controller board is not addressing the Audio Board control section, the onboard 80C535 microprocessor is capable of controlling the audio sections to perform most, not all, of the functions that the Controller Board causes them to perform. The 80C535 microprocessor is provided primarily for diagnostic purposes. Control functions which the microprocessor performs under program control may, as an example, exercise or test the audio channel sections. Such diagnostics may be performed in response to commands received from the controller over the HDLC link. The HDLC link is an FCC protocol.

In addition to providing redundant or secondary control/addressing of control circuits (control latches) the 80C535 microprocessor performs routine control functions associated with the audio sections. These functions include generating chip select and read/write signals, illuminating status indicators, controlling electronic potentiometer levels.

A clock select latch and multiplexer is used to select between redundant sets of master clocking signals common to the entire MultiSite Coordinator switching system. This ensures that each audio section is synchronized with the **TDM** bus. The selected clocking signals are sent to the audio sections through a **CLOCKS** line.



Figure 1 - Audio Board Block Diagram



### CIRCUIT ANALYSIS

## **VOLTAGE REGULATION**

External voltage input levels to the Audio Board are +5 Vdc, +15 Vdc and -15 Vdc. These levels are regulated to produce +5 Vdc (Vcc), +12 Vdc, -12 Vdc and -5 Vdc respectively. Refer to the Schematic Diagram, Sheet 1.

#### + 5 Vdc (Vcc) Regulation

The external +5 Vdc connects to the Vcc regulation circuit from CMP2 | +5EXT through 3 amp fuse F1. Filtering is provided by 100  $\mu$ H inductor L3 and 100  $\mu$ F capacitor C122. Leaded diode D6 removes any negative transients. LED CR1 illuminates when Vcc is present.

The regulated Vcc output is taken from the point labeled Vcc on the Schematic Diagram. The Vcc can be read, using a voltmeter, between **TP25** (Vcc) and **TP21** (GND).

#### + 12 Vdc Regulation

The external +15 Vdc connects to the +12 Vdc regulation circuits from CMP2 | +15EXT through 0.5 amp fuse F2. Filtering, ahead of voltage regulator U2, is provided by 8.2  $\mu$ H inductor L2, 0.1  $\mu$ F capacitor C2 and 100  $\mu$ F capacitor C121. Additional filtering, after U2, is provided by 0.1  $\mu$ F capacitor C3 and 100  $\mu$ F capacitor C124. Leaded diode D2 removes any negative transients. LED CR2 illuminates when +12 Vdc is present.

The regulated + 12 Vdc is taken at the point labeled + 12V on the Schematic Diagram. The + 12 Vdc can be read, using a voltmeter between **TP23** (+ 12 Vdc) and **TP21** (GND).

#### -12 Vdc Regulation

The external -15 Vdc connects to the -12 Vdc regulation circuits from CMP2|-15EXT through 0.5 amp fuse F3. Filtering, ahead of voltage regulator U1, is provided by 8.2  $\mu$ H inductor L1, 0.1  $\mu$ F capacitor

C1 and 100  $\mu$ F capacitor C120. Additional filtering, after U1, is provided by 0.1  $\mu$ F capacitor C4 and 100  $\mu$ F capacitor C123. Leaded Diode D1 provides protection from positive transients. LED CR3 illuminates when -12 Vdc is present.

The regulated -12 Vdc is taken at the point labeled -12V on the Schematic Diagram. The -12 Vdc can be read, using a voltmeter between TP22 (-12 Vdc) and TP21 (GND).

#### -5 Vdc Regulation

The regulated -12 Vdc is applied to the input of voltage regulator U3. Input filtering is provided by 0.33  $\mu$ F capacitor C126. Additional output filtering is provided by 0.1  $\mu$ F capacitor C5 and 100  $\mu$ F capacitor C125. Leaded diode D7 provides protection from positive transients. LED CR4 illuminates when -5 Vdc is present.

The regulated -5 Vdc is taken at the point labeled -5V on the Schematic Diagram. The -5 Vdc can be read, using a voltmeter between **TP24** (-5 Vdc) and **TP21** (GND).

#### DECOUPLING

Decoupling on the Audio Board is provided by 0.01  $\mu$ F capacitors (C6 through C255) connected between all voltage inputs of integrated circuits (U1 through U134) and ground (GND). Refer to the Schematic Diagram, Sheet 1.

#### CONTROL

The Control section of the Audio Board provides control and clock signals to four (4) audio channel sections. The heart of the Control section is microprocessor U118 (SAB80C535). Other microprocessor associated control circuit elements consist of HDLC controller/interface U108 (SAB82525), address decoder U109 (74HC138D), control data latch U115 (multiplex select) (74HC573D), RAM memory U52 (CY7C128-55PC), EPROM U99 (27C256), data multiplexer circuits U106/U107 (74HC157DQ), control signal multiplexer U105 (74HC157DQ) and serial RS-232 port U74 (MAX232C).

#### **Control Registers**

Control registers output control signals to audio channel sections. These control registers consist of Channel Data Latch U112 (74HC573D), Channel Function Latch U113 (74HC573D) and Channel Address Latch U114 (74HC573D). The Channel Address Latch selects, through the CH ADDRESS bus (CA[1:4]), the audio channel section to perform the function specified by the control signals latched in the Channel Function Latch. The Channel Function Latch provides parallel control signals to the audio channel sections through the CH FUNCTION bus (CF[0:5]). Each of the control signals specify a different function to be performed by the audio channel section. The Channel Data Latch stores an 8-bit data word sent to each audio channel section through the DATA LATCH bus (LD[0:7] (refer to the schematic diagram, sheet 2)). The use of the 8-bit word depends on the function selected by the contents of the Channel Function Latch.

#### Controller Board

The module controller Board can also write to the Audio Board control registers and other Audio Board control circuits by imposing data on the **DATA** bus (DB[0:7]) and additional control signals on the **CON-TROL** or **ENABLE** bus (ENBL[0:7]). The address of the Audio Board is set by address DIP switch SW1. The address signals are decoded by address decode logic consisting of 4-bit comparator U103 (74HC85D), enabling NAND gate U101D, flip-flop U123 (74HC74) and other associated NAND gates U102 (74HC00). When the Controller Board places the address, set by SW1, onto data bus DB[0:7]), multiplexers U105, U106 and U107 (74HC157DQ) are controlled to select Controller Board control of the data and control latches.

The circuit consisting of NOR gate U121B (74HC02D), inverter U124F (74HC14D) and latch U119 (74HC2455) is used to latch the switch settings of DIP switch SW1 on to data bus D[0:7]. The setting on SW1 (CMP3|SW[0:7]) is latched onto the microprocessor data bus when the CMP3|!POT\_SW input from address decoder U109 and the CMP3|!WR input from microprocessor U118 goes low.

The signals generated on the control bus (ENBL[0:7]) select the type of programming operation that the Controller Board is to perform on the audio module. For example, the selection of which control register is to be loaded with the signals carried by the **DATA** bus is determined by control lines of the control bus from the Controller Board. The following describes bit significance for control words imposed by the Controller Board on the control bus (ENBL[0:7]).

ENBL0:	Channel Data Latch enable
ENBL1:	not used
ENBL2:	Channel Function Latch enable
ENBL3:	Write Codec enable
ENBL4:	Clock select enable
ENBL5:	not used
ENBL6:	Unselect Card (or Clear Card)
ENBL7:	Channel Address Latch enable

The contents of the Channel Function Latch causes control signals to be generated that directly control an audio channel section addressed by the Channel Address Latch to perform desired functions. The CHANNEL FUNCTION bus (CF[0:5]) output provided by the Channel Function Latch is six (6) bits wide. The functional significance of these six signals (CF0-CF5) with respect to audio sections are set as follows:

- CF0: Selects type of digitized audio converting (e.g. selects between µlaw or Alaw, or between µlaw and no conversion. NOTE: Requires different conversion ROM's (U10, U11).
- CF1: Bus Number/Slot Write Enable (the contents of the Channel Data Latch are to be loaded into the address audio section and used to designate a TDM bus number/slot. Allows WR line to go low.
- CF2: Weighting Table Write enable; ADDR, LATCH ENBL for Weight RAM (Weight RAM has TDMX bus)
- CF3: Write Codec Enable
- CF4: Activates 2175 Hz Tone Generator
- CF5: Enable auxiliary relay (e.g. to light an indicator each time PTT is present).

When the Controller Board is not addressing the Audio Board, multiplexers U105, U106 and U107 (74HC157DQ) select the output of audio processor control/data busses for output to the control register. In this way, local on-board microprocessor U118 can control the audio sections and make them perform some of the functions that the Controller Board can make them perform.

#### Microprocessor

The microprocessor (U118) is primarily for diagnostic purposes. Control functions which U118 performs under program control may, for example, exercise or test the audio channel sections. Such diagnostics may be performed in response to commands received by U118 from the Controller Board over the HDLC link.

In addition to providing redundant or secondary control/addressing of control latches, U112 through U114, microprocessor U118 performs additional routine control functions associated with the audio channel sections. These function include, as an example, generating chip select and read/write signals, illuminating status indicators, controlling levels set by electronic potentiometers. Such routine control signals are sent to the audio channel sections by U118 through an Address/Data bus (D[0:7]).

Receive Data (CMP3|RXD) and Transmit Data (CMP3|TXD) for diagnostics purposes is written to or read from U118 through 9-Pin connector J3, Pins 2 (J3B) and 3 (J3C) and transmitter/receiver U74 (MAX232C). An RS-232 input is applied to J3B, Pin 1 and to U74, Pin 13. A TTL output is realized on U74, Pin 12 (CMP3|RXD). A TTL input on U74, Pin 11 (CMP3|TXD) is converted to an RS-232 output at U74, Pin 14 and Pin 3 (J3C).

#### Data Bus D[0:7] to Backplane

Data Bus to backplane interfacing is accomplished using opto couplers U27A and U18A. To write from data bus D[0:7] to the backplane, microprocessor U118 provides an enable signal (CMP3 | !IO EN) and a write signal (CMP3|! WR). These signals are then input to NAND gate U121D (74HC02D) (Refer to the Schematic Diagram, Sheet 4). The character "!" implies an active low condition. If there is no "!" present then the condition is an active high. NAND gate U121D outputs to 4-bit latch circuit U29 (74HC175). When the two signals, EN and WR, are present the output of U121D (CMP3|10 WR) is applied to U29, Pin 9 (CLK). This latches the 4-bit D[0:3] data into U29. The data is now present on the output side, CMP3|OUT 1, CMP3|OUT 2, CMP3|OUT 3 and CMP|OUT 4 respectively. These four outputs are applied the inputs of opto couplers U27A,B,C,D, Pins 2, 3, 6 and 7 respectively. The 4-bit output data is now written to backplane TDM busses OUTL[1:4] and OUTH[1:4].

To read from the backplane to Data Bus D[0:7] a read enable command is generated through address decoder U109 (74HC138D). This command (CMP3|!IO EN) is applied to an input of NAND gate U121C (74HC02D). A read command (CMP3|!RD) generated by U118 is connected to the other input of U121C. The output of U121C (CMP3|IO RD) is applied to the OE inputs of operational amplifiers U46A,B,C,D. With this signal present, the data on the backplane (INH(1:4) and INL(1:4) is read through opto couplers U18A,B,C,D and operational amplifiers U46A,B,C,D to Data Bus D[7:4].

#### Master Clocking

Master clocking of the audio channel sections ensures that each audio section is synchronized with the TDM bus. Clock selection is accomplished by 4-bit multiplexer U104 (74HC157DQ), Flip-Flop U123B (74HC74), NAND gates U101A/B (74HC00) and inverter U124C (74HC14D). Flip-Flop U123B latches the clock selection controlled by LD[0] and WBCN. These circuits select between redundant sets of master clocking signals common to the entire MultiSite Coordinator II switching system. Clocking signals include Bit Clock A (BCLKA), Bit Clock B (BCLKB), Slot Sync Clock A (SSYNCA), Slot Sync Clock B(SSYNCB), Frame Sync Clock A (FSYNCA) and Frame Sync Clock B (FSYNCB). An inverted Frame Sync Clock (!FSYNC) is provided through inverter U124E (74HC14D). Clocking signals on the outputs of U104 can be monitored as follows:

Test Point	<u>Clock</u>	
<b>TP26</b>	2175 Hz	
<b>TP27</b>	BIT CLOCK	
<b>TP</b> 28	SSYNC	
<b>TP29</b>	FSYNC	

Clock selection responds to the clock select enable bit of the Control/Data Parallel I/O bus. 4-bit multiplexer circuit (U104) selects between clocks under the control of a signal outputted by flip-flop U123 (74HC74), steering circuit U101A/U101B (74HC00) and inverter U124C (74HC14D). Inputs to the steering circuit are LD[0] from multiplexer U106 and WBCN from multiplexer U105. The selected clocking signals are provided to the audio channel section through the "clocks" line.

Spare flip-flop U75A is provided for future use.

The serial control data signal (SERCONDATA) and the Codec Clock (CODEC CLK) is generated through logic array U6 (AMPAL22V10AJC). SER-CONDATA is used in programming codecs (1:4) from the Parallel I/O (PIO) data bus (DB[0:7]) or the microprocessor U118 APD[0:7]. Eight-bit shift register U69 (74HC165D) converts the parallel data at the input (MUX[0:7]) to serial. The CODEC CLK output from U6 signals the codec when to read in SERCONDATA.

### 2175 Hz Tone

A 2175 Hz square wave is input from U104, Pin 4 (TP26) through 0.1 µf capacitor C245 to a tone processing circuit consisting of filter U96 (TP3040), digitally controlled potentiometer U73 (X9103S) and flip-flop U75B (74HC74). The 2175 Hz square wave is filtered through filter U96 to produce a 2175 Hz sine wave. The output of U96, Pin 1 connects to the input of potentiometer U73 where the required level is set. The level from U73 is altered by, first toggling the output of flipflop U75B. U75B output /Q (not Q) is toggled by the CMP3 | SEL-SIN POT signal on the clock input (CLK), Pin 11 and the D[0] signal on the D input, Pin 12. POT\_INC allows the pot value to be incremented. POT\_U/D controls up or down increments. CMP3 |SEL-SIN POT originates from logic array U6, Pin 28 and D[0] originates from data bus D[0:7]. The output on U73, Pin 9 SINOUT connects through 0.01 µf capacitor C235 to the input of operational amplifier U20A (TP42) (refer to Schematic Diagram, Sheet 9 (channel 3)).

#### Manual Reset

A manual reset is provided by pressing switch SW3. Switch SW3 grounds the input to inverter U124A. This signal is buffered and re-inverted by U124A/B to provide !RESET to U118 and other circuitry on the board. When the input of U124A goes to ground the output goes high (CMP|RESET). This resets the HDLC control/interface U108, Pin 17 (SAB82525).

## **AUDIO CHANNEL SECTIONS**

The audio channel sections (4) provide circuitry that processes and digitizes audio signals coming from RF trunked repeater sites or consoles (source) and places the digitized audio on the **TDM** network. The audio channel section also provides circuitry that converts selected digitized audio signals, taken from the **TDM** network (destination), into analog signals and sends the resulting audio signals to an RF trunked repeater site or console for transmission.

The digitized audio portion of the audio channel sections (destination) is preassigned a **TDM** bus number and bus slot, through the Controller Board at the time of power up. Digitized audio signals are continuously broadcast to the **TDM** network whether or not audio is coming in from the site RF receiver or console (source).

#### NOTE

The following circuit analysis uses only one of four audio channel sections (Channel 3). Refer to the Schematic Diagram, sheet 9.

## Source (Analog to Digital)

A balanced pair (e.g. a telephone line) is used to transmit audio signals from RF repeater sites or consoles to an audio channel section. This balanced pair connects to conventional balanced line termination circuitry consisting of (channel 3 only) capacitors C136 and C137, 600 ohm coupling transformer T1, resistor R29 and surge protectors VR3 and VR4. The surge protectors protect the audio section against spikes and transients.

The 600 ohm line termination circuitry couples analog audio signals to programmable electronic potentiometer level adjust (EEPOT) U15 (X91035). U15 can be set by microprocessor U118 specifying a programmable amount of attenuation. Commands for such programmable attenuation adjustment may be communicated from the Controller Board to U118 through the HDLC link. The output of U15 is applied to the input of high pass filter U16A (MC3303D). This active filter has 3-pole bandwidth with an operating frequency of 240 Hz and a gain of 2v/v.

The output of the filter is applied to the input of a compression amplifier/limiter Circuit. This circuit consists of operational amplifiers U16B, U16C, diode package D3, emitter follower transistor Q3 and limiting transistor Q4. The amplifier dc feedback voltage is taken from the collector of limiting transistor Q4 and connected back to the input of U16B between resistor R52 and capacitor C151. As the audio input amplitude increases at U16B, Pin 7, Q4 conducts harder limiting the input to U16B and keeping the output constant. This compression amplifier/limiter circuit produces an audio signal with a relatively uniform average high level, that ensures all digitized audio signals carried by the TDM network have a high signal-to-noise ratio and

also ensures that the analog audio applied to the input of the codec digitizer does not exceed the dynamic range of the digitizer.

Microprocessor U118 can selectively bypass the compression amplifier through analog switch U23B (MAX333). The common (COM) connection of U23B (Pin 8) connects to the input of band pass filter U26 (TP3040). The normally open (NO) connection of U23B (Pin 9) connects to the output of the compressor amplifier at U16B, Pin 7. The normally closed (NC) connection of U23B (Pin 7) connects to the output of the high pass filter U16A. A signal on pin 28 (!COMP-BYP[1]) of U23B from microprocessor U118 causes U23B to select between two outputs: high pass filter U16A and compression amplifier U16B.

The signal to bypass a compression amplifier comes from octal 3-state inverting flip-flop U97. The clock output of U121A, Pin 1 as a result of the inputs, CMP |!WR POTBYPSEL and CMP3 |!WR, clocks U97 to latch information from the D[0:7] bus on to the output !POT-SEL[1:4] or !COMP- BYP[1:4]. !POT-SEL[1:4] connects to one of four electronic potentiometers, in this example U15 (!POT-SEL[3]). !COMP-BYP[1:4] connects to one of four analog switches, in this example U23A and U23B (!COMP-BYP[3]). Notch filter U17 is also bypassed with this signal.

The output of the compression amplifier or high pass filter U16A is applied through analog switch U23B to the input of a 200 - 3400 Hz Band Pass Filter U26 (TP3040). The output of U26 connects to the input of conventional  $\mu$ law PCM digitizer/codec U7 (TP3076A). The codec output provides an input to a demultiplexing network circuit consisting of programmable logic array (PAL) U129 (AMPAL22V10AJC) for application through a conventional buffer to the TDM network. The Controller Board can write instructions to the codec through the Channel Function Latch (U113) and the Channel Address Latch (U114). The codec is programmed for Bus/Slot at power-up by SER-CONDATA. The Codec has four outputs:

- 1) **PCM DATA** in the correct slot (Pin 14);
- 2) !TE active low in correct slot (Pin 15);
- Bus selection (CH\_BUS\_SEL[0:2], Pins 5,17,18):
- 4) PCM DATA SELECT (CMP30|TX\_BUS\_SEL\_[3])

PAL U129 performs Demultiplexing functions for PCM DATA, puts slot-correct data on the bus specified by CH\_BUS\_SEL[0:2] or puts the output of U130 ( $\mu$ P simulated PCM DATA) on the bus specified by CH\_BUS\_SEL[0:2] and the slot specified by !TE (Pin 15 of the codec). This last function is enabled by CPM30|TX\_BUS\_SEL [3].

U130 is selected to output simulated PCM by OR gates U4A through U4D, in this case U4C. These OR gates monitor the write or send data outputs CMP3|!WR\_SD1 through SD4 of address decoder U109. The write signal CMP|!WR originates from U118, Pin 27.

The circuit consisting of flip-flop U24B ((74HC74) and NAND gate U8A (74CH00) allows control information to be written to the Codec. The proper inputs to U8A (CF[3] and CH EN) cause U24B to bring "low" the !CS input to the codec, enabling the codec to read control information.

A **!CLR** signal is generated from 4-bit mux U105 through NAND gate U98D (74HC00) and sent to flip-flop U24B, Pin 13 to deselect the codec after writing to the audio channel.

Each channel shares eight bus drivers for eight TDM busses. Only the bus drivers to be used are enabled. This is accomplished through PAL's U94 and U126 (AMPAL22V10AJC). For channel 3, bus select lines CH3\_SEL[0:2] and !TE[3] connect between codec U7 and PAL's U94 and U126. The enable line output of U94 and U126 (CMP3 | E[1:0]) enables the bus driver to be used only during the slot controlled by channel 3.

Bus transceivers U50 and U51 and enable circuits U94 and U126 are shared among all four audio channel sections to decrease component count, simplify circuit design and reduce the number of components connected directly to the **TDM** busses.

The source portion of the audio channel section (analog input from the repeater site/console) continuously outputs digitized audio signals onto the TDM network on a preassigned TDM bus. All audio channel sections of each Mastr II Interface Module (MIM) and Console Interface Module (CIM) of the system are audio sources that are continuously broadcasting digitized audio information over the TDM network to all other MIM's and all other CIM's. However, no part of the system actually "listens" to any of these continuously active audio channels until digital messages (i.e., slot assignment messages) are sent over the message network indicating that a call is active. Such slot assignment messages for active calls specify a TDM bus number/bus slot and also convey information (i.e. radio transceiver group information) that causes all MIM's and CIM's that need to be involved with a call to begin "listening" to the appropriate TDM bus slots. They

convert the digitized audio signals contained in these slots into analog audio signals and provide the analog audio signals to an RF repeater or console assigned to handle the call (RF repeaters and associated RF working channels are also assigned in response to an initial slot assignment message).

### Destination (Digital to Analog)

The destination portion of the audio channel section includes TDM bus transceivers U50 and U51. It includes serial parallel conversion U22 (XC03070), read only µLaw-to-linear conversion lookup table PROM U10/U11 (CY7C291-35), read/write slot/bus weight lookup table U13, high speed multiplier/accumulator U12 (CY7C510-55) and digital range checker/limiter U21 (refer to the schematic diagram sheet 10). The destination portion of the audio channel section also includes digital-to-analog converter (DAC) U25 (AD7840), additional scaling and filtering through U26 (TP3040), notch filter circuitry through switched capacitor filter U17 (MF5CWM), 2175 Hz tone generation through variable gain amplifier U20A and a 600 ohm line termination circuit T2 (refer to the schematic diagram, sheet 9). The TDM bus receivers U50 and U51 receive signals from all TDM busses. The outputs of this bank of bus receivers (TDMX BUS[0:7]) are applied to serial inputs of a bank of eight (8) shift registers, U22 (XC303070) and associated latch circuits. The shift registers and latch circuits arrangement is accomplished using a VLSI programmable ASIC chip, U22 in this case. There is one shift register and associated latch for each of the individual TDM busses within the TDM network. Shift registers operate at the TDM bus timing bit rate and function as serial-to-parallel converters that continuously shift in a slot worth of PCM digitized audio and convert it to an 8-bit wide parallel output format. Each shift register is 8-bits wide and can hold all PCM data bits for a particular bus slot.

The latch circuits are clocked at the TDM bus slot timing rate, and operate to latch the parallel output signals provided by shift registers corresponding to a particular bus slot. At the conclusion of a TDM bus duration, each of the latch circuits contain an 8-bit parallel word corresponding to the contents of a single slot of a single associated TDM bus. The latch circuits together provide, in parallel, the slot contents of all TDM busses for the last TDM bus slot.

The data latched by the latch circuits is multiplexed in sequence to the address inputs of a  $\mu$ law/linear conversion lookup table within PROMS U10 and U11 (CY7C291-35). This is implemented at a bit clock rate that is a multiple of the TDM bus slot timing. For example, for 32 TDM busses the bit clock rate must be 32 times the TDM slot rate. All circuits from the latch circuits of U22 to multiplier/accumulator U12 are all synchronized to operate at this rate. The parallel output of one latch circuit at a time is enabled onto a multiplexed address bus (CMP32|MD[O:9]). The multiplexing is performed under the control of a counter (part of U22) clocked at the bit clock rate previously described. Incrementing the counter from zero to a maximum value causes the TDM bus data corresponding to the following sequence of TDM bus number/bus slots to be applied to the address input of the lookup table:





The signals carried by the multiplexed address bus are used to address the lookup table. The Look up table comprises a 512 by 16-bit ROM (U10 and U11) and performs a linearizing function (LND []). More particularly, the lookup table stores conventional conversion data used to map a  $\mu$ Law digitized representation to simplify the mathematical operations performed by multiplier/accumulator U12 (CY7C510-55).

The Controller Board can select, through the Channel Function Latch bit CFO, a different mapping (e.g., no mapping at all to accommodate digital data of the type transmitted by a modem of a remote RF transceiver data terminal).

The LND output of the lookup table (CMP32|LND[0:15]) is applied to one input of multiplier/accumulator U12 operating in sync with the bit clock and with the multiplexed address bus. Another input of the multiplier/accumulator receives an 8-bit weighting signal provided by the output of slot/bus weight lookup table within Read/Write memory U13 (CY7C128-55PC). The Lookup table of U13 consists a 256 X 8 bit RAM addressed by the output of programmable logic U22 previously described. The address information is provided by the U22 encoding the TDM bus number and TDM slot number. The address supplied to lookup table in U13 specifies a particular location with the lookup table corresponding to a TDM bus number/slot combination.

Two write cycles of the CH DATA bus are used by the Controller Board to rewrite a location within the memory. Once the Controller Board writes the appropriate address information into the Channel Address Latch selecting an appropriate audio channel section, the Controller Board latches a bus number/bus slot value into the Channel Data Latch. The Controller Board then writes an appropriate control word into the Channel Function Latch. This control word specifies that the contents of the Data Latch are to be latched by the audio channel section as a bus number/bus slot. This control word may also specify the CF1 bit to be asserted. The Controller Board then causes the Data Latch to latch the new weighting factor value and writes a further control word into the Channel Function Latch. This control word specifies CF2 = 1, causing a write

TDM BUS 0,	Slot 0 Weight Factor	(8 bits)
TDM BUS 1,	Slot 0 Weight Factor	(8 bits)
TDM BUS 2,	Slot 0 Weight Factor	(8 bits)
TDM BUS 3,	Slot 0 Weight Factor	(8 bits)
TDM BUS 4,	Slot 0 Weight Factor	(8 bits)
TDM BUS 5,	Slot 0 Weight Factor	(8 bits)
TDM BUS 6,	Slot 0 Weight Factor	(0 bits)
TDM BUS 7,	Slot 0 Weight Factor	(0 bits)
TDM BUS 0,	Slot 1 Weight Factor	(8 bits)
TDM BUS 1,	Slot 1 Weight Factor	(8 bits)
	•	
	•	
	•	
TDM BUS 6,	Slot 31 Weight Factor	(8 bits)
TDM BUS 7,	Slot 31 Weight Factor	(8 bits)

Figure 3 - Memory Mapping

to memory. One of the ASIC's previously described passes the bus number/bus slot address through to the address inputs of memory. It also multiplexes the contents of the Channel Data Latch onto the data input/output lines of the memory so it can be written into the memory in response to the memory write enable signal.

Figure 3 is a memory map of memory U13. Memory U13 includes individual memory locations uniquely corresponding to TDM bus number/slots (i.e., input sources). These memory locations are organized with respect to the address lines from the counter. This is so the counter, as it is incremented, addresses a sequence of memory locations. These memory locations then correspond to the sequence of data provided by latch circuits over the address bus. Memory U13 stores blocks of latched data corresponding to bus slots, each memory location, includes a weight value for each of the individual TDM slots.

Addressing of memory U13 by the counter results in the following sequence of weighting factors to be outputted from the lookup table (U13), where each weighting factor is indicated by an ordered pair of TDM bus number, TDM slot number:

WF(0,0);
WF(1,0);
WF(2.0):
•
•
•
WF(7,0); WF(0,1);
WF(1,1); WF(2,1);
•
•
•
WF(7,1);
WF(0,2);
WF(1,2);
•
•
• WF(7,31);

High-speed multiplier/accumulator U12 operates at the bit clock rate to multiply the sequences of outputs of the lookup tables together and to sum the products into an output register. The high-speed multiplier/accumulator performs the following sum of products calculation once for each TDM bus frame:

$\{LND[TDM BUS (0),$	Slot (0)]	* WF(0.0)} +
(LND) TDM BUS (1).		* WF(1,0) +
(LND TDM BUS (2),	Slot $(0)$	* $WF(2,0)$ +
	•	
	•	
	•	
(LNDITDM BUS (7)	Slot $(0)$	* WF(7 0) +
(LNDITDM BUS (0)	Slot $(0)$	* WF(0,1)
$\{LND[TDM BUS (1)\}$	Slot $(1)$	* WE(0,1) +
$\{I, ND\}$ TDM BUS (2)	Slot $(1)$	* WF(0,1) +
$(\operatorname{Lind}[1\operatorname{Div} \operatorname{DOS}(2),$	5101 (1)]	vvr(0,1) +
	•	
	•	
	•	
$\{LND[TDM BUS (7),$	Slot $(1)$ ]	* $WF(7,1)$ +
$\{LND[TDM BUS (0),$	Slot (2)]	* WF(0,2) +
$\{LND[TDM BUS (1),$	Slot (2)]	* WF(1,2) +
	•	
	•	
	•	

#### {LND[TDM BUS (7),Slot (31)]\* WF(7,31)} +

The values of weighting factors |WF(0,0)...WF(7,31) determine which TDM bus numbers/bus slots (i.e., PCM digitized audio channels carried by the TDM network contributes to the sum accumulated by the multiplier/accumulator. When the destination served by the audio board is inactive, all of the weighting factors have zero values and the output of the multiplier/accumulator is zero. When the destination served by the audio board is active, one or more of the weighting factors (i.e., the weighting factors corresponding to the TDM bus number(s)/bus slot(s)) are given non-zero weights such that only those bus/slots contribute to the output of the multiplier/accumulator.

Once per TDM frame, the multiplier/accumulator provides a summation output to the input of digital range checker/limiter U21 (XC302070). Range checker/limiter U12 comprises a programmable ASIC that operates at the TDM bus slot rate to check the magnitude of the summation output and if necessary, to substitute a predetermined maximum output value for any value exceeding the dynamic range of Digital-ToAnalog Converter (DAC) U25 (AD7840). DAC U25 converts, at the TDM slot rate, the output of the range checker/limiter into an audio signal (14 bit precision) and provides an analog output, DAC OUT (AN[2]) to low pass filtering circuit U26 (Fco = 3400 Hz). The output of U26 connects to the input of 2175 Hz notch filter U17 (NOTCH IN) and to the NC (Pin 4) connection of analog switch U23A. The notch filter, switched capacitor filter U17, can be bypassed through analog switch U23A by the COMP BYP[3] signal from microprocessor U118. The COM connection of U23A (Pin 3) connects through summing resistor R267 to the input of operational amplifier U20B (TL082A).

Presettable counter U125 (74HC161), driven by CMP3 |CLKOUT from U118, produces a filter clock (FLTR CLK) for U17, Pin 8.

The 2175 Hz tone is generated in response to channel function latch bit CF4 (U14B, Pin 4) and is used to control the repeater transmitter during operation in the remote repeat mode. While the RF site is also capable of operating in the local repeat mode, the remote repeat mode is used in the multisite switch configuration to permit MIM's to remotely control when their associated repeater transmitters are on the air and transmitting RF signals modulated with audio. The Controller Board controls the addition of a remote repeat tone (2175 Hz) to the audio channel output.

Tone generating circuitry for the 2175 Hz remote repeat control tone consists of AND gate U14B (74HC08C), flip-flop U24A (74HC74) and multivibrators U18A and U18B (74HC123A), bilateral switches U19A, B, C, D (4066BM) and operational amplifier U20A (TL082A). This circuitry selectively generates and applies a 2175 Hz tone to the audio path through summing resistor R265 to the input of operational amplifier U20B. Bilateral switches U19A/B/C are switched on/off by multivibrators U18A/B to provide gain adjust (refer to Figure 4). This is accomplished by switching in or out the appropriate feed back resistance for operational amplifier U20A. U19D enables 2175 Hz tone to be summed into the output audio path. The 2175 Hz remote keying involves a three tone level sequence as shown in Figure 5.

The resulting analog audio and tone output to line termination circuit T2 is applied to the associated RF repeater transmitter audio input through an audio link.



Figure 4 - Operational Amplifier Gain Control



### **UNSUPPORTED CIRCUITS**

The unsupported circuits on this 4-channel audio board consist of four (4) auxiliary relay circuits and a clock failure detection circuit.

## **Auxiliary Relays**

The auxiliary relay circuits are located in the four (4) audio channel sections. These circuits consist of AND gates U14C, U37C, U60C and U87C (74HC00C), transistors Q1, Q5, Q9 and Q16 and relays K1 through K4 (LM44B00).

## **Clock Failure Detect**

The clock failure detect circuit is part of the control section. It consists of 4-input AND gate U116B (74HC20).

# QUICK REFERENCE TO TROUBLESHOOTING

Symptoms	Action		
Power LED's (CR-4) not lit	Check power fuses F1-F3		
Sanity LED (CR6) not blinking	Check for bent pin(s) on EPROM U99		
Card remains in reset; CR5 stays on	Check for bent pin(s) on EPROM U99		
No channels Working	1. Verify correct dip switch setting.		
	2. Reset commanding controller board to make certain that the audio board has been initialized.		
	3. Verify slot allocation table at MOM PC. If slot allocations must be ad- justed, after the allocations have been set, all controller boards must be reset.		
	4. Verify that CR5 on the audio board flashes briefly when audio is routed out of a channel dedicated to that audio board. If not, this most likely is not an audio board problem.		
Audio on some but not all channels.	1. Verify slot allocations as describe above.		
	2. Verify incoming audio to each particular audio board channel by check- ing at the appropriate test point.		
	3. Verify outgoing audio from each particular audio board channel by check- ing at the appropriate test point.		

Continued

Continued

# QUICK REFERENCE TO TROUBLESHOOTING

Symptoms	Actic	n	
· · · · · · · · · · · · · · · · · · ·	AUDIO BOARD TEST POINTS		
	Signal	Test Point	
	Vcc	TP25	
	-5V	TP24	
	+ 12V	TP23	
	-12V	TP22	
	GND	TP21	
	:KES	1250	
	Chann	al 1	
	SITE IN	TP19	
	SITE OUT	TP15	
	Chann	e <u>l 2</u>	
	SITE IN	TP7	
	SITE OUT	<b>TP10</b>	
	<u>Chann</u>	<u>el 3</u>	
	SITE IN		
	SILEOUI	1P5	
	Chann	al 4	
	SITE IN	TP17	
	SITE OUT	TP19	
	Clocks		
	2175	<b>TP26</b>	
	BIT_CLOCK	TP27	
	SSYNC	TP28	
	FSYNC	TP29	
	NOTE, The SITE IN	maint for each shared and if the	
	from the base station on a	point for each channel specifies audio coming	
	specifies audio going from the MSC II to the base station of the		
		the wide if to the base station or console.	



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## VOLTAGE REGULATORS U001/U003 19A134718P2/P1 (MC7912CT/MC7905CT)





I. COMMON 2.OUTPUT 3. INPUT

VOLTAGE REGULATOR U002 19A134717P2(MC7812CT)



I. INPUT

2. COMMON

- 3. OUTPUT
- 4. TAB COMMON

QUAD 2-INPUT OR GATE U004 19A703483P311 (74HC32D)





 $\begin{array}{l} \text{PIN } 14 = \text{V}_{\text{CC}} \\ \text{PIN } 7 = \text{GND} \end{array}$ 

#### QUAD SPST ANALOG SWITCH U005/U023 344A3113P101 (MAX333CWP)



#### PIN CONFIGURATION

#### CMOS PROGRAMMABLE ARRAY LOGIC U006/U094/U126/U127P/U129P/U131P/U133P 344A3377G1,G2,G4/3137P1 (PAL22V10AJC)

#### PIN IDENTIFICATION







#### CODEC/FILTER U007/U030/U053/U076 344A3105P1 (TP3076A)





QUAD 2-INPUT NAND GATE U008/U031/U054/077/U098/U101/U102 19A703483P302 (74HC00)





-

SERIAL CONFIGURATION PROM U009SP/U032SP/U055SP/U078SP 344A3377G53128P1 (XC1736A)

DATA C	1	ъ	vcc
	2 7	γÞ	VPP
RESET/OE	3 (	\$Þ	<u>CEO</u>
ČE C	4 !	۶Þ	GND



EPROM (256K X 8) U010SP/U033SPU011SP/U034SP/ U056SP/U080SPU057SP/U079SP 344A3377G6&G7/3118P1 (CY7C291-35)

#### **Pin Configurations**



Logic Block Diagram



#### DIGITAL 16X16 MULTIPLIER ACCUMULATOR U012/U035/U058/U081 344A3112P1 (CY7C510-55)





1

### **READ/WRITE MEMORY**

U013/U036/U052/U059/U082

19A702934P2/P4 (CY7C128-55PC)





<sup>A</sup> 0∼ <sup>A</sup> 10	ADDRESS INPUTS
R/W	READ/WRITE CONTROL INPUT
ŌĒ	OUTPUT ENABLE INPUT
<u>cs</u>	CHIP SELECT INPUT
1/01 ~1/08	DATA INPUT/OUTPUT
V <sub>cc</sub>	POWER (+5 VDC)
GND	GROUND

IC DATA

#### QUAD 2-INPUT AND GATE **U014/U037/U060/U084** 19A703483P305 (74HC08C)

PIN ASSIGNMENT			
AI	1.	14	Vcc
ві	2	13	B4
YI	3	12	<b>A</b> 4
A2[	4	П	) Y4
B2 [	5	10	<b>B</b> 3
Y2[			) A3
GND			DY3
			I

FUN	FUNCTION CHART			
INP	UT	DUTPUT		
A	B	Y		
L	L	L		
H	L	L		
Н	H	H		



.

PIN 14 = Vcc PIN 7 = GND

#### DIGITALLY CONTROLLED POTENTIOMETER U015/U038/U061/U073/U085 19A705180P102 (X9103S)



U/D

VSS

VH

FUNCTIONAL DIAGRAM



,

#### PIN NAME

VH	HIGH TERMINAL OF POT
VW	WIPER TERMINAL OF POT
VL	LOW TERMINAL OF POT
VSS	GROUND
VCC	SYSTEM POWER
U/D	UP / DOWN CONTROL
INC CS	WIPER MOVEMENT CONTROL CHIP SELECT

LBI-38664

#### OPERATIONAL AMPLIFIER U016/U039/U062/U086 19A704883P2 (MC3303D)



OUT Ουτ [ ]14 ı 4 13 2 INPUTS INPUTS 4 L 3 2 Vcc  $V_{EE}$  GND 11 4 10 5 INPUTS, INPUTS 3 2 3 6 9 олт 2 О 3 8 7 (TOP VIEW)

SWITCHED CAPACITOR FILTER U017/U040/U063/U088 344A3124P1 (MF5CWM)





PIN CONNECTIONS

#### MONOSTABLE MULTIVIBRATOR U018/U041/U064/U089/U110/U111 19A704380P321 (74HC123A)



**Truth Table** 

Inputs			Outputs		
Clear	A	B	0	۵	
L	X	x	L	н	
x	н	X	L	н	
x	X	lι	L	н	
н	L	1	л	J	
н	1	н	л	ۍ ۲	
1	L	н	л	ν	

.

#### BILATERAL SWITCH U019/U042/U065/U090 19A702705P4 (4066BM)





LOGIC DIAGRAM



(1/4 OF DEVICE SHOWN)

CONTROL	SWITCH
0	OFF
I	ON

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#### OPERATIONAL AMPLIFIER U020/U043/U066/U091 344A3070P2 (TL082A)



#### DIGITAL LOGIC CELL ARRAY U021/U022/U044/U045/ U067/U068/U092/U093 344A3129P1 (XC3020-70)





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Unprogrammed IOBs have a default pu5-up. This prevents an undefined pad level for unbonded or unused IOBs. Programmed outputs are default slew-simted.

CMOS DUAL D FLIP-FLOP W/SET-RESET U024/U047/U070/U075/U095/U123 19A704380P302 (74HC74)



	Inp	uts		Out	puts
PR	CLR	CLK	D	Q	۵
L	н	x	x	н	L
Н	L	x	X	L	н
L	L	X	X	H.	н•
н	н	Ť	н	н	L
н	н	Ť	L	L	н
н	н	L	X	00	δo

### DIGITAL TO ANALOG CONVERTER (DAC) U025/U048/U071/U083 344A3123P1 (AD7840)





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LBI-38664

TRANSMIT (HP) FILTER/RECEIVER (LP) FILTER U026/U049/U072/U087/U096 344A3122P1 (TP3040)



OPTO-COUPLER U027/U028 344A3071P2 (LQ66-4)



IC DATA

#### QUAD FLIP-FLOP WITH CLEAR U029 19A704380P310 (74HC175)

PIN ASSIGNMENT				
Reset C	1.	16	Þ vcc	
00 0	2	15	2 03	
$\overline{00}$	э	14	<u> </u>	
DO <b>C</b>	4	13	0 03	
ם וס	5	12	202	
ז וס	6	n	0 02	
01 0	7	10	0.02	
GND C	8	9	Clock	

FUN	ICT	ЮN	TAI	BLE

inputs		Out	puts
Reest Clock	D	a	۵
LX	x	L	н
н	н	H	L
н	Ľ	L	н
ΗL	X	no ch	enge



.

EXPANDED LOGIC DIAGRAM



## LBI-38664

### QUAD 3-STATE NON-INVERTING BUFFER U046 19A703471P305 (74HC126)

PIN ASSIGNMENT				
and	1.		ber	
A1 0	2	13	Dœ4	
- 11 0	3	12	þ.	
atz₫	4	11	D 16	
- 42 (	5	18	) ac a	
720	\$	9	14	
÷	7	1	013	

нста нста						
Ineuto		Owner	Marca (			
	OE	Y		٥٤	¥	
×	L	н	H	н	м	
L.	L	L	L L	н	L	
X	Ħ	2	x	ι	2	



.







#### 8-BIT SHIFT REGISTER U069/U128/U130/U132/U134 19A703987P322 (74HC165D)



		1						
Operation	Oursout Cay	Stages D <sub>A</sub> Og	А-Н	SA	Clock Inhibit	Clock	Senal Shift/ Parawai Load	
Asynchronous Parallel Load	h	a b	8h	X	X	X	L	
Senal Shift via Clock	Q <sub>Gn</sub> Q <sub>Gn</sub>	L QAn H QAn	X X	L H	L	2	H H	
Senal Shift via Clock Inhibit	Q <sub>Gn</sub> Q <sub>Gn</sub>	L QAN H QAN	××	L H	7	L	н н	
Inhibited Clocx	inge	no che	x x	××	HX	X H	н н	
No Clocx	inge	no cha	X	X	L	ī.	н	

X = don't care

QArrQGn = Data shifted from the preceding stage

#### RS-232 TRANSMITTER/RECEIVER U074 19A149446P2 (MAX232C)





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LBI-38664

#### OCTAL 3-STATE INVERTING D FLIP-FLOP U097 19A704380P315 (74HC564DQ)

#### PIN ASSIGNMENT

Output Enable	1.	20	
∞ t	Ż	19	<b>7</b> 00
D1 [	3	18	101
C [	4	17	] 02
C C C	5	16	103
D4 E	6	15	04
DS [	7	14	3 05
D6 [	8	13	3 06
D7 <b>C</b>	9	12	] 07
GNO	10	11	Cock

#### FUNCTION TABLE

	Output		
Output Enable	Cock	D	٩
L	77	ม เ	L H
L	сн.~	x	no change
н	X	X	Z

X=don't care Z=high impacance



D O

IC DATA

#### EPROM (256K) U099SP

344A3377G8 (27C256(A704305P5))



PIN NAME

.

A0-A14	ADDRESSES
CE	CHIP ENABLE
OE	OUTPUT ENABLE
0 <sub>0</sub> - 0 <sub>7</sub>	OUTPUTS
# LBI-38664

### 4-BIT MAGNITUDE COMPARATOR U103 19A703483P319 (74HC84D)

PIN ASSIGNMENT			
20	1.	18	}. <u>.</u>
4<1.	2	15	bu .
4-4-0	3	14	þæ -
م م د ا	4	13	112
ا <sub>اس</sub> ه < ۸	5	12	DAT
*- <b></b>	£	11	Das -
ا يو×>▲	7	10	D M
- <b>20</b> [	•	1	3 100



•

#### FUNCTION TABLE

	Curra	incutar		C.	icading in			CAVED UT	
A3. 83	A2. 12	A1, B1	A0. B0	1 A>8.	A = 8 m	A<8.	A>800.	A-Sour	A<2m
A3>83	X	X	X	x	X.	x	H	1	1
A3<23	X	x	x		x	x ·			2
A3-83	A2>82	x	l x	x I	x	- <del>-</del>		•	
A3-83	A2<82	x	t x	x	, r	Ŷ			
A3-83	A2=82	1 A1>81	i i	X				·	<u> </u>
AJ-83	A2-82	AICBI	x x	Î Î	÷	- Ç			
A3-83	A7=87	A1-81	40.500	12	÷.	<b>•</b>			
A3+83	A7=87	A1 - 81	40 - 80	1 0	÷.	- ÷		L	L
A3- 83	A2=82	A1-81	40-80	<del></del>	<del>~ ^ _</del>		<u> </u>	<u> </u>	H
A3-87	A2 81	A1 - B1	10-00			- L	H	L	H
47 - 97			20-20		L	- M	L	L	H
N= 83	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	A1= 61	A0 = 80	н	L	- L	H	L	L 3
A3-83	A2-62	A1-81	A0-80	н	L.	н	L	L	1
A3=83	A2-82	A1-81	A0 80	X	H	x	ĩ	Ĥ.	ī

X=Don't Care

### IC DATA

#### QUAD 2-INPUT DATA SELECTOR/MUX U104/U105/U106/U107 19A703471P323 (74HC157DQ)

#### **PIN ASSIGNMENT**







X = don't care A0-A3, 80-83 = the territis of the respective Deta-Word Inouts.



#### SERIAL COMMUNICATION CONTROLLER U108S 19A149956P1 (SAB82525N)



LBI-38664

#### **ADDRESS DECODER U109** 19A704445P101 (74HC138D)



### FUNCTION TABLE

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н Η Н

Н

Н Η

Outputs CS3 A2 A1 A0 Y0 Y1 Y2 Y3 Y4 Y5 Y6 Y7 Х Н н Η х Х Н н н H н н н н Н X Х Х н н Н н H н Н Н х Х Х н Н н Η Н н н н L L Н н н L. Н н Н Н н н Η L L Н L Н н н Н L н H L н H L

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Н L

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 $V_{CC} = Pin 16$ GND = Pin 8

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L = Low Level (steady state)

X = Don't Care

Inputs

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CS1 CS2

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#### OCTAL 3-STATE NON INVERTING TRANSMIT LATCH U112/U113/U114/U115 19A703471P318 (74HC573D)

PIN ASSIGNMENT		
	1 . 20	Pra
en (	2 19	j]ac ∣
a: [	3 18	Dai
62 (	4 17	Dez 🛛
===Q	5 16	βœ
₽ Q	8 IS	þ.
as [	7 14	) es
DK 🕻	1 13	þœ
87 Q	8 12	þa7
ee (	18 11	LATON EMARLE

	Inevia		Output
Ourupurt Enable	Latch Enable	D	٩
L	н	н	-
L	н	L	L
L	L	x	
н	x	x	z

EXPANDED LOGIC DIAGRAM

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#### DUAL 4-INPUT NAND GATE U116 19A703483P308 (74HC20)

PIN	ASSIGNMENT

AT	1.	14	٩
810	2	13	102
×	3	12	
C1 (	4	11	) and
91 Q	5	10	1=2
T1 [	6		þa
800	7		hus.

LOGIC DIAGRAM

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PIN 14= Vcc PIN 7= GND PINS 3, II NO CONNECTION

NC=NO CONNECTION

#### FUNCTION TABLE

	Inp	with a		Output
	8	С	D	Y
L	X	X	x	н
X	L	X	X	н
X	X	L	X	н
x	X	X	L	н
н	н	н	н	ι

TRANSCEIVER U117 19A149953P201 (DS3896)





LBI-38664

#### OCTAL 3-STATE NONINVERT BUS TRANSCEIVER U119 19A703471P108 (74HC245S)

DIRECTION	• 20	] Vcc
AI 1 2	19	DOUTPUT ENABLE
A2[] 3	18	рві
A30 4	17	<b>J</b> B2
A40 5	16	DB3
A 50 6	i 15	<b>JB4</b>
7 D94	14	<b>JB5</b>
A7 C 8	13	Ве
A80 9	12	DB7
GNDC	10 11	вв

PIN ASSIGNMENT



.

PIN 10 = GND PIN 20 = Vcc

FUNCTION TABLE			
CONTROL	L INPUTS		
OUTPUT ENABLE	DIRECTION	OPERATION	
L	L	DATA TRANSMITTED FROM BUS B TO BUS A	
ι	н	DATA TRANSMITTED FROM BUS A TO BUS B	
н	x	BUSES ISOLATOR (HIGH IMPEDANCE STATE)	

X=DON'T CARE

# IC DATA

#### QUAD 2-INPUT NOR GATE U121 19A703483P301 (74HC02D)

PIN ASSIGNMENT				
YI	1.	• 14	]Vcc	
AIC	2	13	IY4	
в1 (	3	12	]84	
Y2[	4	н	<b>]</b> A4	
A5[	5	10	<u>1</u> 73	
B5[	6	9	]B3	
GND [	7	8	] A3	

FUNCTION DIAGRAM		
INPUTS	OUTPUT	
A B	Y	
LL	н	
LH	L	
нс	L	
нн	L	

LOGIC DIAGRAM

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#### HEX SCHMITT TRIGGER INVERTERS U124 19A703483P321 (74HC14D)

#### PIN ASSIGNMENT

A101.	14 D VCC
T1 0 2	13 DAS
A2 [ 3	12 176
Y2 🕻 4	11 045
лцs	10 Å 75
3 I CT	2 þ.a.
900 🛛 7	8 þ. y 4

#### FUNCTION TABLE

Input	Output
A	Y
L	н
н	L

LOGIC DIAGRAM



LBI-38664

# PRESETTABLE COUNTER U125 19A703987P306 (74HC161)

# PIN ASSIGNMENT

Reset (	1.	16	<sup>I</sup> Vœ
Clock	2	15	Ripple Carry
PO 2	3	14	3 00
P1 [	4	ъ	J Q1
P2 0	5	12	102
P3 1	6	11	1 03
Eneble P E	7	10	Eneble T
GND I	8		Lond

#### FUNCTION TABLE

		Ourput			
Clock	Reset	لعما	Enebie P	Enable T	Q
5	L	X	X	X	Read
	H	L	X	X	Lond Preset Dets
	H	н	j N :	н	Count
~ 1	н (	H H	L	X	No Count
5	1 H 1	H	1 x 1	L	No Count

\*HC152 and HC153 only. HC150 and HC161 are Asynchronous-R Devices

H-high level

L= tow level X= don't care



#### LOGIC DIAGRAM

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# PARTS LIST

4-CHANNEL AUDIO BOARD 19D903302P1, REV. EM1

	l	1	C217	
SYMBOL	GE PART NO.	DESCRIPTION	C218 and C219	19A705205P211
			C220	19A702052P1
C001 thru C005	19A702052P26	CHIP: .luF	C221 C222	19A702052P14 19A702052P14
C006 thru C119	19A702052P14	CHIP: .01µF	and C224	1987020528105
C120	19A703314P12	LEADED: 100µF	and C229	1
C122	19A703314P12	LEADED: 100µF	C231	19A705205P18
C123 and C124	19A705205P211	CHIP: 47µF	C234	198702052914
C125	19A705205P6	CHIP: 10µF	and C236	
C126	19A705205P12	CHIP: .33µF	C237	19A702061P33
C127 thru C132	19A702052P26	CHIP: .1µF	and C238	193701050505
C133	19A705205P12	CHIP: .33uP	6233	198702052820
thru C135			C241	198702052014
C136 and C137	198705205P211	CHIP: 47µF	and C242	
C138	19A702052P14	CHIP: 01uF	and (244)	194/02061P49
thru Cl47	19A702052P14		C244	193702052826
C148	198702052P1	CHIP: 220PF	C246	19A705205P18
C149	19A702052P14	CHIP: .01µP	C247	19A705205P211
C150			C248	19A702052P14
C153	19A702052P105	CHIP: 1000pF	C249	19A702052P26
C155 and C156	19A705205P18	CHIP: 4.7µF	C250 thru C252	19A702052P14
C157	19A705205P211	CHIP: 47µF	C253	19A705205P211
C158 thru C163	19A702052P26	CHIP: .luf	C254 thru C256	19A702052P14
Cl64 thru Cl66	19A705205P12	CHIP: .33µF	C257 thru C261	19A705205P6
C167 and C168	198705205P211	CHIP: 47µF	C266	19A702052P14
C169 thru C179	19A702052P14	CHIP: .01µF	CR01 thru	19A703595P10
C180	19A705205P2	CHIP: luF	D001	19870005382
C181	19A702052P1	CHIP: 220PF	thru D005	
C184	19A702052P105	CHIP: 1000pF	D006	T324ADP1041
C186 and C187	19A705205P18	CHIP: 4.7µF	and D007	19370005252
C188	19A705205P211	CHIP: 47µF	and D014	19470003352
C189 thru C194	19A702052P26	CHIP: .luF		
C195 thru	193705205P12	CHIP: .33µF	F001 F002 and	19A134961P22 19A134961P10
C198	193702052014		F003	
C199 and	19A705205P211	снігоци Снір: 47µF	J001 and	19B801587P4
C201 thru C208	19A702052P14	CHIP: .01µF	J002 J003	19B209727P37

\*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES

SYMBOL	GE PART NO.	DESCRIPTION
C209 and C214	19A702052P26	CHIP: .luf
C215 thru C217	19A705205P12	CHIP: .33µF
C218 and C219	19A705205P211	CHIP: 47µF
C220	19A702052P1	CHIF: 220pF
C221	19A702052P14	CHIP: .01µF
C222 and C224	19A702052P14	CHIP: 220PF
C226 and C229	19A702052P105	CHIP: 1000pF
C231 thru C234	19A705205P18	СНІР: 4.7µР
C235 and C236	19A702052P14	CHIP: .01µF
C237 and C238	19A702061P33	CHIP: 27pF
C239	19A702052P26	CHIP: .luF
C240	19A702052P105	CHIP: 1000pF
C241 and C242	19A702052P14	CHIP: .01µF
C243 and C244	19A702061P49	CHIP: S6pP
C245	19A702052P26	CHIP: .luF
C246	19A705205P18	CHIP: 4.7µP
C247	19A705205P211	CHIP: 47µF
C248	19A702052P14	CHIP: .01µF
C249	19A702052P26	CHIP: .1µF
C250 thru C252	19A702052P14	CHIP: .01µF
C253	19A705205P211	CHIP: 47µF
C254 thru C256	19A702052P14	CHIP: .01µF
2257 thru 2261	19A705205P6	CHIP: 10µF
266	19A702052P14	CHIP: CAP .01UµF
CRO1 Chru CRO6	19A703595P10	HLMP-1301-010
001 hru 0005	19A700053P2	CHIP DIODE
0006 and 0007	T324ADP1041	LEADED DIODE
0008 nd 0014	19A700053P2	CHIP DIODE
001	198134961922	PUSES
002	198134961910	PTICP 53
nd 003	198134961910	FUSE .SA
001 nd 002	198801587P4	96 PIN CONN
003	19B209727P37	D8-9

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# PARTS LIST

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# LBI-38664

SYMBOL	GE PART NO.	DESCRIPTION	SY	MBOL	GE PART NO.		DESCRIPTION
		RELAYS	RO	039	19A702931P301	CHIP RESISTOR	10.0K 1%
K001	19B235621P1	RELAY LM44BOO CP CLARE	RO	040	19B800607P563	CHIP RESISTOR	56K 5%
K004			RO	041	19A702931P301	CHIP RESISTOR	10.0K 1%
]			RO	042	198800607P225	CHIP RESISTOR	2.2M 5%
LOO1 and	19A700021P28	CHIP IND 8.2 uH	RO	043	19B800607P102	CHIP RESISTOR	1.0K 5%
L002			RO	044	19A702931P401	CHIP RESISTOR	100.0K 1%
L003	19A149806P2	LEADED IND 100µH	RO	945	198800607P563	CHIP RESISTOR	56K 5%
			RO	46	19A702931P301	CHIP RESISTOR	10.0K 1%
LED1 thru	19A703595P10	HLMP-1301-010	RO	947	19A702931P295	CHIP RESISTOR	9.53K 1%
LED4	1		RO	48	19A702931P461	CHIP RESISTOR	422K 1%
0001	10370007650		RO	49	19A702931P259	CHIP RESISTOR	4.02K 1%
and 0002	19870007892	CHIP TRANSISTOR	RO	150	19B800607P151	CHIP RESISTOR	150 5%
0004	198702524P3		20	52	19A702931P301	CHIP RESISTOR	10.0K 1%
0005	19A700076P2	CHIP TRANSISTOR	RO	53	1987029319401	CHIP RESISTOR	100.0K 1%
and Q006			an R0	d 54	100019511551	CHIP RESISTOR	10.0K 14
0008	19A702524P3	CHIP PET	RO	55	19A702931F385	CHIP RESISTOR	75 04 19
0009	19A700076P2	CHIP TRANSISTOR	RO	56	19A702931P374	CHIP RESISTOR	57.6K 1%
and Q010			RO	57	19B800607P564	CHIP RESISTOR	560K 5%
0012	19A702524F3	CHIP FET	RO	58	19B800607P223	CHIP RESISTOR	22K 5%
Q013			RO	59	19A702931P301	CHIP RESISTOR	10.0K 1%
0015 thru	19A700076P2	CHIP TRANSISTOR	RO	60	19A702931P401	CHIP RESISTOR	100K 1%
Q018			RO	61	19A702931P301	CHIP RESISTOR	10.0K 1%
			RO	62			
R001	19A702931P230	CHIP RESISTOR 2.0K 1%	RO	63	19B800607P151	CHIP RESISTOR	150 5%
R002 and	19A702931P266	CHIP RESISTOR 4.75K 1%	RO	64	344A3206P4	LEADED 11.0K	.1%
RCO3			RÓ	65	198702931P360	CHIP RESISTOR	12.7K 1%
R004	198/029319230	CHIP RESISTOR 2.0K 1%	ROG	66	19A702931P301	CHIP RESISTOR	10.0K 1%
R005	1987029312401	CHIP RESISTOR 100K 1%	ROG	69 70	19B800607P273	CHIP RESISTOR	27K 5%
and R007	198/029317301	CHIP RESISTOR 10.0K 1%	th R07	70 ru 77	1947029312266	CHIP RESISTOR	4.7K 5%
R008	19B800607P151	CHIP RESISTOR 150 5%	R07	78	19A702931P301	CHIP RESISTOR	10.0K 1%
R009	19A702931P401	CHIP RESISTOR 100.0K 1%	R07	79	19A702931P266	CHIP RESISTOR	4.7K 5%
R010	19A702931P360	CHIP RESISTOR 12.7K 1%	ROS	80 d	19A702931P301	CHIP RESISTOR	10.0K 1%
R011	19A702931P301	CHIP RESISTOR 10.0K 1%	ROS	81			
R012 and R013	1988006079151	CHIP RESISTOR 150 5%	R08 and R08	82 1 83	19B800607P102	CHIP RESISTOR	1.0K 5%
R014	19B800607P273	CHIP RESISTOR 27K 5%	ROS	84	19A702391P176	CHIP RESISTOR	604 1%
R015 thur	19A702931P266	CHIP RESISTOR 4.7K 5%	ROS	85			
R22			R08	86	19A702931P320	CHIP RESISTOR	15.8K 1%
R023	19A702931P301	CHIP RESISTOR 10.0K 1%	ROS	37	19A702931P407	CHIP RESISTOR	115K 14
R024	19A702931P266	CHIP RESISTOR 4.7K 5%	ROS	38	19A702931F374	CHIP RESISTOR	57.6K 1%
and	198/029319301	CHIP RESISTOR 10.0K 1%	ROS	39	19A702931P385	CHIP RESISTOR	75.0K 1%
R027 and	19B800607P102	CHIP RESISTOR 1.0K 5%	R09 R09		19A702931P320 19A702931P360	CHIP RESISTOR CHIP RESISTOR	15.8K 1% 41.2K 1%
R028			ROS	2			
R029 and	19A702391P176	CHIP RESISTOR 604 1%	ROS	93	19A702931P320	CHIP RESISTOR	15.8K 1%
R030			R09	*4	19B800607P333	CHIP RESISTOR	33K 5%
R031	19A702931P320	CHIP RESISTOR 15.8K 1%	R09	5	19A702931P301	CHIP RESISTOR	10.0K 1%
R032	19A702931P407	CHIP RESISTOR 115K 1%	R09	6	1988006079563	CHIP RESISTOR	56K 5%
RU33	19A702931P360	CHIP RESISTOR 41.2K 1%	R09	7	19A702931P301	CHIP RESISTOR	10.0K 1%
8035	1987029319200	CHIP RESISTOR 560K 5%	R09	8	19B800607P225	CHIP RESISTOR	2.2M 5%
R036	1987029319360	CHIP RESISTOR 41 24 14	R09		198800607P102	CHIP RESISTOR	1.0K 5%
and R037		REFEIN 71.2N 13	R10	,	1988006079543	CHIP RESISTOR	100.0K 1%
R038	19B800607P333	CHIP RESISTOR 33K 5%	R10	2	1987029319301	CHIP RESISTOR	JUN 35
				-		CALL RESISTOR	10.0N 18

# PARTS LIST

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SYMBOL	GE PART NO.	DESCRIPTION		SYMBOL	GE PART NO.	DESCRIPTION
R103	19A702931P295	CHIP RESISTOR 9.53K 14		R167	19B800607P564	CHIP RESISTOR 560K 5%
R104	19A702931P461	CHIP RESISTOR 422K 1%		R168	19B800607P223	CHIP RESISTOR 22K 5%
R105	19A702931P259	CHIP RESISTOR 4.02K 1%		R169	19A702931P301	CHIP RESISTOR 10.0K 1%
R106	19B800607P102	CHIP RESISTOR 1.0K 5%		R170	19A702931P401	CHIP RESISTOR 100X 1%
R107	19A702931P301	CHIP RESISTOR 10.0K 1%		R171	19A702931F371	CHIP RESISTOR 53.6K 1%
R108	19A702931P401	CHIP RESISTOR 100.0K 1%		R174	19A702931P301	CHIP RESISTOR 10.0K 1%
R109	19A702931P301	CHIP RESISTOR 10.0K 1%		R175	344A3206P4	LEADED 11.0K .1%
R110				R176	19A702931P360	CHIP RESISTOR 12.7K 1%
R111	19A702931P385	CHIP RESISTOR 75.0K 1%		R177	19B800607P151	CHIP RESISTOR 150 5%
R112	19A702931P374	CHIP RESISTOR 57.6K 1%		R178 and	19A702931P301	CHIP RESISTOR 10.0K 1%
R113	19B800607P564	CHIP RESISTOR 560K 5%		R179		
R114	19B800607P223	CHIP RESISTOR 22K 5%		R180	1988006079273	CHIP RESISTOR 27K 5%
R115	19A702931P301	CHIP RESISTOR 10.0K 1%		R182	1987029319266	CHIP RESISTOR 4.7K 5%
P117	1987029319401	CHIP RESISTOR 100K 1		R183	1987029319266	CHIP RESISTOR 10.0K 14
and R118	1947029319301	CHIP RESISTOR 10.0K 1%		thru R190	1547015511100	CHIP RESISTOR 4./K 5%
R119	19B800607P151	CHIP RESISTOR 150 5%		R191 and	19B800607P102	CHIP RESISTOR 1.0K 5%
R120	344A3206P4	LEADED 11.0K .1%		R192		
R121	19A702931P360	CHIP RESISTOR 12.7K 1%		and	19A702931P301	CRIP RESISTOR 10.0K 14
R122	19A702931P301	CHIP RESISTOR 10.0K 1%		R194	1017022010154	
R125 R126	198800607P273 198702931P266	CHIP RESISTOR 27K 5% CHIP RESISTOR 4.7K 5%		and R196	198/0239101/6	CRIP RESISTOR 604 1%
thru R133				R197	198800607P223	CHIP RESISTOR 22K 5%
R134	19A702931P301	CHIP RESISTOR 10.0K 1%		R198	19A702931P348	CHIP RESISTOR 30.9K 1
R135	19A702931P266	CHIP RESISTOR 4.7K 5%		R199	19A702931P401	CHIP RESISTOR 100.0K 1%
R136	19A702931P301	CHIP RESISTOR 10.0K 1%		R200	19A702931P295	CHIP RESISTOR 9.53K 1%
R137	19A702931P301	CHIP RESISTOR 10.0K 1%		R201	19A702931P393	CHIP RESISTOR 90.9K 14
R138	198800607P102	CHIP RESISTOR 1.0K 5%		R202	344A3206P4	LEADED 11.0K .1%
R139 R140	19A702391P176	CHIP RESISTOR 604 1%		R203 and R204	19B800607P102	CHIP RESISTOR 1.0K 5%
R141				R205	19A702931P407	CHIP RESISTOR 115K 1%
R142	19A702931P320	CHIP RESISTOR 15.8K 1%		R206	19A702931P320	CHIP RESISTOR 15.8K 1%
R143	19A702931P407	CHIP RESISTOR 115K 1%		R207	19B800607P333	CHIP RESISTOR 33K 5%
R144 and R145	19A702931P360	CHIP RESISTOR 41.2K 1%		R208 R209	1987029319301 1988006079563	CHIP RESISTOR 10.0K 1%
8146	1937029219220			R210	198800607225	
R147	1987029318360	CHIP RESISTOR 15.8K 18		R211	1987029319301	CHIP RESISTOR 10 OF 15
R148	1988006072333	CHIP RESISTOR 312 58		R212	1988006079102	CHIP RESISTOR 1.0K 54
R149	19A702931P301	CHIP RESISTOR 10.0K 19		R213	19A702931P401	CHIP RESISTOR 100.0K 1%
R150	1988006079563	CHIP RESISTOR 56K 5%		R214	19A702931P301	CHIP RESISTOR 10.0K 1%
R151	19A702931P301	CHIP RESISTOR 10.0K 1%		R215	1988006072563	CHIP RESISTOR 56K 5%
R152	19B800607P225	CHIP RESISTOR 2.2M 5%		R216	19A702931P266	CHIP RESISTOR 4.7K 5%
R153	19B800607P102	CHIP RESISTOR 1.0K 5%		R217	1937029312461	CHIP RESISTOR 422K 1
R154	19A702931P401	CHIP RESISTOR 100.0K 1%		R218	19A702931P259	CHIP RESISTOR 4.02K 1%
R155	1988006079563	CHIP RESISTOR 56K 5%		R219	19A702931P301	CHIP RESISTOR 10.0K 1%
R156	19A702931P301	CHIP RESISTOR 10.0K 1%		R220	19A702931P266	CHIP RESISTOR 4.7K 5%
R157	19A702931P295	CHIP RESISTOR 9.53K 1%		R221	19A702931P401	CHIP RESISTOR 100.0K 1%
R158	19A702931P461	CHIP RESISTOR 422K 1%		R222 thru	19A702931F301	CHIP RESISTOR 10.0K 1%
R159	19A702931P259	CHIP RESISTOR 4.02K 1%		R224		
R160	19B800607P102	CHIP RESISTOR 1.0K 5%		and R226	198/029319230	CHIP RESISTOR 2.0K 1%
R163	19A702931P301	CHIP RESISTOR 10.0K 1%	11	R227	1917029319220	CHID RECYCRAD A AF 14
R163	19A702931P401 19A702931P301	CHIP RESISTOR 100.0K 1% CHIP RESISTOR 10.0K 1%		thru R229		MAIF REDISTOR 2.0K 1%
and R164				R230 thru	19A702931P301	CHIP RESISTOR 10.0K 1%
R165	19A702931P385	CHIP RESISTOR 75.0K 1%		R241		
R166	19A702931P374	CHIP RESISTOR 57.6K 1%				
	1					

# PARTS LIST

# LBI-38664

SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL
R246	19B800607P122	CHIP RESISTOR 1.2K 5%	U004
R249			0005
R250	19A702931P301	CHIP RESISTOR 10.0K 1%	U006P
R252 and R253	19A702931P266	CHIP RESISTOR 4.7K 5%	U007
R254	19B800607P102	CHIP RESISTOR 1.0K 5%	0008
R255	19A702931P371	CHIP RESISTOR 53.6K 1%	U009SP
R256 thru R258	19A702931P401	CHIP RESISTOR 100K 1%	U010SP
R259	19A702931P266	CHIP RESISTOR 4.7K 5%	U011SP
R260 and R261	19A702931P401	CHIP RESISTOR 100K 1%	U012 U013
R262	19A702931P393	CHIP RESISTOR 90 9K 18	U014
R263	344A3206P3	LEADED RESISTOR 12.4K 18	U015
R264	19A702931P371	CHIP RESISTOR 53.6K 1%	U016
R265	19A702931F348	CHIP RESISTOR 30.9K 1%	0017
R266	19A702931P401	CHIP RESISTOR 100.0K 1%	0018
R267 and R268	19A702931P393	CHIP RESISTOR 90.9K 1%	U019 U020
R269	344A3206P3	12 44 16	U021
R270	19A702931P371	CHIP RESISTOR 53 6K 18	0022
R271	19A702931P348	CHIP RESISTOR 30 9K 18	U023
R272	19A702931P401	CHIP RESISTOR 100 OK 18	0024
R273	1947029319393	CHIP RESISTOR 90.9K 1%	U025
and R274			U026 U027
R275	344A3206P3	12.4K .1%	and U028
R276	19A702931P371	CHIP RESISTOR 53.6K 1%	U029
R277	1947029312348	CHIP RESISTOR 30.9K 1%	0030
R278	19A702931P401	CHIP RESISTOR 100.0K 1%	U031
R279 and R280	19A702931F393	CHIP RESISTOR 90.9K 1%	U032SP
R281	344A3206P3	12.4K .1%	U033SP
R282 thru R285	19B800607P122	CHIP RESISTOR 1.2K 5%	U034SP
R286	19B800607P273	CHIP RESISTOR 27K 5%	0035
R287	19A702931P230	CHIP RESISTOR 2.0K 1%	U036
R288	19B800607P273	CHIP RESISTOR 27K 5%	U037
Ř289	19A702931P401	CHIP RESISTOR 100K 1%	0038
R290	19A702931P230	CHIP RESISTOR 2.0K 1%	U039
R291	19B800607P151	CHIP RESISTOR 150 5%	0040
R292	19A702931P301	CHIP RESISTOR 10.0K 1%	0041
R295			U042
			U043
SWOL	19A149955P1	5W9955P1	U044
SW02	19A149923P1	1 POS	0045
SW03			U046
T001	344A3106P1	LXFMRA3106P1	1049
thru TOOS			U049
			U050 and
thru	344A3367P1	TP1622P1	U051
TP49			0052
		INTEGRATED CIRCUITS	0053
0001	19A134718P2	MC7912CT TO-220 MOT	U054
0002	19A134717P2	MC7812CT TO-220 MOT	U055SP
0003	19A134718P1	MC7905CT TO-220 NOT	

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	GE PART NO.	DESCRIPTION
	19A703483P311	74HC32D 50-14 MOT.TI.RCA
	344A3113P101	MAX333CWP SO-W-20 MAXIM
	344A3377G1/	PAL22VIOAJC PLCC-28 AMD, CYPRESS, TI
	34483105P1	7930763 DIP-20 NATIONAL
	1987034839302	74HC00 SOLC-14 MOT TH BCA
	344A3377G5/	XC1736A DIP-8 XILINX
	344A3128P1	
	344A3377G6/ 344A3118P1	CY7C291-35 DIP-24 CYPRESS or etc.
	344A3112P1	CY7C510-55 PLCC-68 CYPRESS or etc.
	19A702934P2	CY7C128-55PC DIP-24 CYPRESS or etc.
	19A703483P305	74HC08C SOIC-14 MOT,TI,RCA
	19A705180P102	X91035 SOIC-14 XICOR
	19A704883P2	MC3303D SOIC-14 MOT
	344A3124P1	MP5CWM SO-W-14 NATIONAL
	19A704380P321	74HC123A SOIC-16 MOT,TI,RCA
	19A702705P4	4066BM SO-14 MOT, RCA
	344A3070P2	TLO82A SO-8 TI
	344A3129P1	XC3020-70 PLCC-84 XILINX
	344A3129P1	XC3020-70 PLCC-84 XILINX
	344A3113P101	MAX333CWP SO-W-20 MAXIM
	3445313251	74HC74 SOIC-14 MOT,TI,RCA
	3443312281	AD7840 PLCC-28 ANALOG DEVICES
	3448307192	LIOSS-4 DID-15 HD TI
	19A704380P310	74HC175 SOIC-16 MOT.TI.RCA
	344A3105P1	TP3076A DIP-20 NATIONAL
	19A703483P302	74HC00 SOIC-14 MOT,TI,RCA
	344A3377G5/	XC1736A DIP-8 XILINX
	3448312881	
	344A3118P1	CITCIPIESS DIP-24 CIPRESS or etc.
1	344A3377G7/ 344A3118P1	CY7C291-35 DIP-24 CYPRESS or etc.
	344A3112P1	CY7C510-55 PLCC-68 CYPRESS or etc.
	19A702934P2	CY7C128-55PC DIP-24 CYPRESS or etc.
	198703483P305	74HC08C SOIC-14 MOT,TI,RCA
	19A705180P102	X9103S SOIC-14 XICOR
	19A704883P2	MC3303D SOIC-14 MOT
	344A3124P1	MP5CWM SO-W-14 NATIONAL
	19A704380P321	74HC123A SOIC-16 MOT,TI,RCA
	19A702705P4	4066BM S0-14 MOT,RCA
	344A3070P2	TLO82A SO-8 TI
	344A3129P1	XC3020-70 PLCC-84 XILINX
	344A3129P1	XC3020-70 PLCC-84 XILINX
Ì	1987034712305	74HCI26 SOIC-14 MOT,TI,RCA
	3448312301	74HC74 SOIC-14 MOT,TI,RCA
	344A3122P1	TP3040 PLCC-28 ANALOG DEVICES
	19A149953P202	DS3897M SO-W-20 NATIONAL
		•• •• •• ••
	19870293424	CY7C128-55PC SOIC-W-24 CYPRESS or etc.
	344A3105P1	TP3076A DIP-20 NATIONAL
	19A703483P302	74HC00 SOIC-14 MOT,TI,RCB
	344A3377G5/	XC1736A DIF-8 XILINX
	JANJI20P1	

# PARTS LIST

SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
UOS6SP	344A3377G6/ 344A3118P1	CY7C291-35 DIP-24 CYPRESS or etc.	U112	19A703471P318	74HC573D SOIC-W-20 MOT.TI.RCA
U0575P	344A3377G7/	CY7C291-35 DIP-24 CYPRESS or etc.	thru Ull5	19A703471P318	
	344A3118P1		U116	19A703483P308	74HC20 SOIC-14 MOT,TI,RCA
0058	344A3112P1	CY7C510-55 PLCC-68 CYPRESS or etc.	U117	19A149953P201	DS3896 SO-W-20 NATIONAL
1060	19A702934P2	CY7C128-55PC DIP-24 CYPRESS or etc.	U118S	19A705828P1	SAB80C535 PLCC-68 SIEMENS
0061	1987051809102	VALCORC SOIC-14 MOT,TI,RCA	U119	19A703471P108	74HC2455 SOIC-W-20 MOT,TI,RCA
U062	19A704883P2	MC3303D SOIC-14 MOT	0121	19A703483P301	74HC02D SOIC-14 MOT,TI,RCA
0063	344A3124P1	MP5CWM SO-W-14 NATIONAL	0123	19A704380P302	74HC74 SOIC-14 MOT,TI,RCA
U064	19A704380P321	74HC123A SOIC-16 MOT,TI,RCA	U125	1987039879306	74HC14D SOIC-14 MOT,TI,RCA
<b>V065</b>	19A702705P4	4066BM S0-14 MOT, RCA	U126P	344A3377G3/	PAL22VIOAIC PLCC-28 AND CYPERSE TO
0066	344A3070P2	TLO82A SO-8 TI		344A3137P1	
UO67 and	344A3129P1	XC3020-70 PLCC-84 XILINX	U127P	344A3377G4/ 344A3137P1	PAL22V10AJC PLCC-28 AMD, CYPRESS, TI
0068			U128	19A703987P322	74HC165D SO-W-16 MOT,TI,RCA
1070	1987039879322	74HC165D SO-W-16 MOT,TI,RCA	U129P	344A3377G4/ 344A3137P1	PAL22V10AJC PLCC-28 AMD, CYPRESS, TI
U071	3448312391	74HC74 SOIC-14 MOT,TI,RCA	<b>U130</b>	19A703987P322	74HC165D SO-W-16 MOT.TI.RCA
0072	344A3122P1	TP3040 PLCC-20 NATIONAL	U131P	344A3377G4/	PAL22V10AJC PLCC-28 AMD, CYPRESS, TI
0073	19A705180P102	X9103S SOLC-14 XLCOR		344A3137P1	
U074	19A149446P2	MAX232C SOIC-W-16 MAXIM	0132	1947039879322	74HC165D SO-W-16 MOT,TI,RCA
U075	19A704380P302	74HC74 SOIC-14 MOT,TI,RCA	0135F	344A3137P1	PAL22VIOAJC PLCC-28 AMD, CYPRESS, TI
U076	344A3105P1	TP3076A DIP-20 NATIONAL	U134	19A703987P322	74HC165D SO-W-16 MOT,TI,RCA
0077	19A703483P302	74HC00 SOIC-14 MOT,TI,RCA			ZENER DIODES
U078SP	344A3377G5/ 344A3128P1	XC1736A DIP-8 XILINX	VRO1 thru VRO8	19A700083P101	ZENIER
0079SP	344A3377G7/ 344A3118P1	CY7C291-35 DIP-24 CYPRESS or etc.			
UOSOSP	344A3377G6/ 344A3118P1	CY7C291-35 DJP-24 CYPRESS or etc.	XF01 thru XF06	19A116688P2	FUSE CLIPS CLIPS
0081	344A3112P1	CY7C510-55 PLCC-68 CYPRESS or etc.			IC SOCKETS
U082	19A702934P2	CY7C128-55PC DIP-24	x0003	19A700156P15	SOCKET DIP-8
0083	344A3123P1	AD7840 PLCC-28 ANALOG DEVICES	XU010 and	19A700156P19	SOCKET DIP-24-N
1085	1987051800100	74HC08C SOIC-14 HOT,TI,RCA	XU011		
0086	19A704883P2	MC3303D SOLC-14 XICOR	XU032	19A700156P15	SOCKET DIP-8
U087	344A3122P1		XU033 and	19A700156P19	SOCKET DIP-24-N
U088	344A3124P1	MF5CWM SO-W-14 NATIONAL	XU034	103200155515	
U089	19A704380P321	74HC123A SOIC-16 MOT,TI,RCA	XU055	198700156919	SOCKET DIP-8
UO 90	19A702705P4	4066BM SO-14 MOT, RCA	and XU057	158/00150715	SUCRET DIF-24-N
U091 .	344A3070P2	TLO82A SO-8 TI	XU078	19A700156P15	SOCKET DIP-8
U092 and U093	344A3129P1	XC3020-70 PLCC-84 XILINX	XU079 and XU080	19A700156P19	SOCKET DIP-24-N
U094P	344A3377G2/	PAL22V10AJC PLCC-28 AMD, CYPRESS, TI	XU099	19A700156P3	SOCKET DIP-28
U095	1987043808302	744074 5010-14 NOT TI DOL	XULOS	344A3339P3	SOCKET PLCC-44
U096	344A3122P1	TP3040 PLCC-20 NATIONAL	XU118	344A3339P5	SOCKET PLCC-68
<b>U097</b>	19A704380P315	74HC564DO SOIC-W-20 MOT.TI.RCA			
U0995P	344A3377G8	27C256(A704305P5) DIP-28 INTEL,TI	¥001	19A702511G15	LY2511G5 11.0592NHZ DALE,CTS,GE
U101 and U102	19A703483P302	74HC00 SOIC-14 MOT,TI,RCA	¥002	19 <b>1</b> 702511G5	LY2511G5 11.520MHz DALE,CTS,GE
U103	19A703483P319	74HC85D SO-16 MOT.TI.RCA			
U104 thru	19A703471P323	74HC157DQ SOIC-16 MOT,TI,RCA			
U1085	19A149956P1	SAB82525N 5010-44 9754545			
U109	19A704445P101	74HC138D SO-16 MOT,TI,RCA			
U110 and U111	19A704380P321	74HCl23A SOIC-16 MOT,TI,RCA			



RUNS ON SOLDER SIDE RUNS ON BOTH SIDES RUNS ON COMPONENT SIDE



### **OUTLINE DIAGRAM**

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**AUDIO BOARD** 19D903302G1 Sheet 1 of 2

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#### OUTLINE DIAGRAM





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(19D905504, Sheet 1, Rev. E&M)

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States - - -

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SCHEMATIC DIAGRAM









(19D905304, Sheet 4, Rev. E&M)



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<sup>(19</sup>D905504, Sheet 5, Rev. E&M)



**AUDIO BOARD** 19D903302G1

(19D905504, Sheet 6, Rev. E&M)



<sup>(19</sup>D903304, Sheet 7, Rev. E&M)



#### **AUDIO BOARD** 19D903302G1

(19D903304, Sheet 8, Rev. E&M)

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CHP31-WT\_0(0:7)

CHP31 [DACD[0:13]



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(19D903304, Sheet 9, Rev. E&M)



#### **AUDIO BOARD** 19D903302G1

(19D905504, Sheet 10, Rev. E&M)



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19D903302G1

(19D903504, Sheet 11, Rev. E&M)

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SCHEMATIC DIAGRAM



**AUDIO BOARD** 19D903302G1

(19D903304, Sheet 12, Rev. E&M)

# ADDENDUM NO. 1 TO LBI-38664 (PCMS)

This addendum makes a correction in Table 2 - Connector J2 Pin Definitions. The fifth listing below the heading "Connector Pin" should read "J2-1B" instead of "J2-1A".

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# 1. INTRODUCTION

This addendum incorporates high-level information on Audio Board 19D903302P3. This Audio Board replaces Audio Board 19D903302P1 in all CEC/IMC Digital Audio Switch applications. Backwards compatibility with the P1 Audio Board is retained. A revised maintenance manual completely documenting P3 Audio Board will be issued at a later date. Contact your service representative for additional information.

The CEC/IMC Audio Board is used to interface four (4) channels of audio to the CEC/IMC backplane system. These audio channels may support a radio system such as an EDACS site, a dispatch console such as a C3 Maestro console, or some other external device such as a logging recorder. The board can be configured to interface channels 1 - 4 or 5 - 8 or 9 - 12, etc. by changing the board address at DIP switch SW1. Refer to LBI-38664 or LBI-38938 for a more detailed description.

In comparison to the P1 Audio Board, the P3 Audio Board improves the features and/or circuit specifications of the following:

- 2175 Hz Notch Filter Circuit
- S/N Ratio on the Channel Outputs
- System TDM Bus and Clock Loading
- Power-Up / Live Insertion Microprocessor Reset
- Indication LEDs
- Test Point Access

All modifications for features on the P1 Audio Board have been incorporated into the P3 Audio Board. In addition, hardware has been added to the P3 Audio Board to support the following features:

- E & M Signaling
- ID Indicator LED
- Vcc Voltage Monitor
- Futurebus Driver Disable

NOTE

Many of the above features require supporting firmware for full implementation.

# 2. IMPROVEMENT DETAILS

#### 2.1. ALC CIRCUIT

An Automatic Level Control (ALC) circuit exists on the input section of each audio channel on the Audio Board. This circuit maintains a "not to exceed" analog signal input to the CODEC integrated circuit. The CODEC digitizes the analog signal for placement on the CEC/IMC TDM bus network. Distortion will occur if the analog signal into the CODEC is too high. The analog threshold occurs at approximately +5 dBm into the channel inputs.

The P1 Audio Board contained this functionality. However, the ALC enable was tied to the notch filter enable for each channel such that if one was enabled then both were enabled. Hardware on the P3 Audio Board allows independent enable/disable control of the ALC circuit and the notch filter circuit. This separated enable/disable control is supported in CEC/IMC firmware version 2.0 and later. ALC is enable/disabled from the CEC/IMC Manager (MOM PC).

### ADDENDUM NO. 2 TO LBI-38664 (PCMS)

#### **2.2. NOTCH FILTER (2175 Hz)**

A 2175 Hz notch filter is located in the output section of each audio channel on the Audio Board. When this filter is enabled from the CEC/IMC Manager (MOM PC), all 2175 Hz components in the output (transmit) audio signal are attenuated. This filtering occurs prior to the summation of the 2175 Hz keying tone (if enabled). Notching the 2175 Hz components in the transmit audio prevents destructive interference with the summed 2175 Hz keying tone.

The 2175 Hz notch filter circuit on the P3 Audio Board is enhanced. Additionally, the notch filter can be enabled and disabled independently of the channels ALC circuit, as described in the previous section. The 2175 Hz notch filter is enabled/disabled from the CEC/IMC Manager (MOM PC).

#### 2.3. S/N IMPROVEMENTS

The signal-to-noise ratio of the P3 Audio Board's channel outputs is improved over the P1 Audio Board. These improvements are most evident when using the board with a headset-equipped dispatch console.

#### 2.4. TDM BUS AND CLOCK LOADING

Capacitive loading of the Futurebus lines on the CEC/IMC Backplane by the Audio Board is improved (reduced) when the P3 Audio Board is utilized. This improves the performance of multiple backplane systems.

#### 2.5. POWER-UP/LIVE INSERTION

Power-up/live insertion issues with the P1 Audio Board were addressed on the P3 Audio Boards by two means. First, an IC was added to monitor the Vcc voltage supply during power-up and live insertions. This IC will also reset the microprocessor during low voltage or "brown-outs". Second, the P3 Audio Board is equipped with extended power pins on the 96-pin DIN connectors. This implements a "make first and break last" connection for the power and ground supplies.

#### 2.6. LED INDICATORS

LED colors and functions between the P1 and P3 Audio Boards are different. The P3 Audio Board conforms to the standards initiated by Controller Board 19D903299P3. Green LEDs replace the red LEDs found on the P1 board. Also, the blinking "RUN" LED on the P1 Audio Board is replaced by an LED that remains illuminated when the board is functioning properly. This "RUN" LED on the P3 Audio Board will turn off if the board is in a reset condition or not functioning properly.

Two new LED identifiers were added to the Audio Board for board identification and channel address write:

The new "ID" LED functions exactly the same as the "ID" LED on the P3 Controller Board - it blinks when enabled from the CEC/IMC Manager (MOM PC). This feature provides quick visual board IDentification within the system. Firmware version 2.1 or later is required.

The new channel address write LED is labeled "CARD SEL" on the front panel of the P3 Audio Board. It indicates when the associated Controller Board is controlling some function on the board. For example, this LED will illuminate when the Controller Board commands the P3 Audio Board to route audio on a channel's output (when a call is made).

The "RESET" and "RUN" LEDs on the P1 Audio Board are combined to a single "RUN" LED on the P3 Audio Board. When the "RUN" LED is lit, the microprocessor is running. When it is off, the P3 Audio Board is in a reset condition.

#### 2.7. Vcc VOLTAGE MONITOR

The P3 Audio Board is equipped with a Vcc voltage monitor IC which monitors the +5 Vdc Vcc supply voltage. If the voltage drops too low during a power glitch or power loss, the board will go into reset until the condition clears.

### ADDENDUM NO. 2 TO LBI-38664 (PCMS)

#### 2.8. FUTUREBUS DRIVER DISABLE

The Futurebus drivers on the Audio Board interface the board to the TDM buses on the Backplane. On the P3 Audio Board, a driver disable is initiated automatically when the Audio Board is in reset. This prevents the P3 Audio Board from causing interference on the TDM buses during power-up and reset conditions.

#### NOTE

Since this feature is activated by a board reset, the Controller Board must first enable the Futurebus drivers before any audio can be routed by the Audio Board. Firmware prior to version 3.0 (G10) requires the Controller Board to be reset after an Audio Board reset to properly initialize this function. Version 3.0 (and later) corrects this issue to allow an Audio Board to be reset and properly initialize itself without resetting the Controller Board.

#### 2.9. E & M SIGNALLING

Audio Board 19D903302P3 supports the 'M' lead keying function for E & M signalling support. This feature provides a relay closure when audio is routed out of the respective channel on the Audio Board. For example, if the Audio Board is configured to interface channels 1 - 4 of site 1, when a call is made to site 1 channel 1 from the CEC/IMC (console originated or multisite originated), relay 1 will close for the duration of the call. A separate relay is provided for each of the four channels.

Additional notes about E & M signalling:

- E & M signalling is selectable on a per channel basis from the CEC/IMC Manager (MOM PC).
- E & M signaling is required for Digital Dispatch Interface Modules (DVIMs).
- Audio Relay Concentrator Card 19D904546G1 (option MSSU3G) is utilized to interface E & M signals to external devices. See LBI-38884 for additional details.

#### 2.10. TEST PORT CONNECTOR

A Test Port Connector is provided on the P3 Audio Board to enhance access to the test points on the board. This connector is accessible through the face plate. It is used with Test Point Breakout Option MSTS3N which includes Test Point Breakout Board 19D904176G1 and associated cables.

# **3. COMPATIBILITY**

Audio Board 19D903302P3 is fully backwards compatible with Audio Board 19D903302P1. A P1 Audio Board can be replaced by a P3 Audio Board equipped with version 2.0 or later firmware.

#### NOTE

An initialization discrepancy exists for systems running Version 2.x firmware (earlier than G10). See section **2.8 FUTUREBUS DRIVER DISABLE** for details.

The P3 Audio Boards must be used with applications that require E & M signalling such as DVIU equipment. In addition, P3 Audio Boards are favored for CIMs (Console Interface Modules) and XLTRs (Translators) due to the improved S/N ratio at the channel outputs.

### ADDENDUM NO. 2 TO LBI-38664 (PCMS)

### **3.1. FIRMWARE**

The following minimum firmware revisions must be maintained to provide correct functionality in the 19D903302P3 Audio Boards:

- Controller Board (U58, U59) 344A3567G5 and 344A3568G5 (Version 2.03)
- Controller Board (U3) 344A3565G4 (Version 2.00)
- Audio Board (U99) 344A3564G3 (Version 2.00)

The P3 Audio Board will support these and all later revisions of CEC/IMC firmware.

#### NOTE

A reset procedure must be followed for any interface modules (MIM, CIM, etc.) containing 19D903302P3 Audio Boards *and* a Controller Board with version 2.x firmware. When installing or resetting a P3 Audio Board, the Controller Board must be reset *after* the Audio Board has been installed and/or reset.

# 4. INSTALLATION PROCEDURES

The P3 Audio Board was designed to directly replace all earlier revisions of the P1 Audio Board. P3 Audio Boards should be installed in exactly the same manner as the older P1 boards. Refer to LBI-38938 for DIP switch settings - P3 Audio Board DIP switches are set in the same manner as on P1 Audio Board.

If the correct firmware has not been supplied with the P3 Audio Board, remove EPROM U99 from its socket and replace it with a new EPROM containing the revised firmware. **CAUTION: PIN 1 OF THE EPROM MUST BE INSERTED INTO PIN 3 OF THE SOCKET SO THE EPROM IS "RIGHT JUSTIFIED" IN THE SOCKET.** 

#### NOTE

A reset procedure must be followed for any interface modules (MIM, CIM, etc.) containing 19D903302P3 Audio Boards *and* a Controller Board with version 2.x firmware. When installing or resetting a P3 Audio Board, the Controller Board must be reset *after* the Audio Board has been installed and/or reset.

#### 4.1. SYSTEM INTERRUPTIONS

When replacing a CEC/IMC Audio Board, the four channels of audio interfaced by that board will not be available while the board is removed. If the Audio Board interfaces to four (4) channels of a site audio, all receive and transmit audio to those four channels will be lost until the installation is complete. If the Audio Board is used within a CIM or XLTR interface module, all transmit and receive audio for that single console will be lost until the installation is complete.

#### 4.2. INSTALLATION VERIFICATION

- 1. Observe the LED indicators on the P3 Audio Board. All LEDs should be lit solid (not blinking) except for the "ID" and "CARD SEL" LEDs.
- 2. From the CEC/IMC Manager (MOM PC), verify the HDLC Channel B link for the newly installed board becomes active.
- 3. Verify the clock LEDs on each Audio Board are lit. These LEDs are marked "2175", "BCLK", "SSYNC" and "FSYNC".

### ADDENDUM NO. 3 TO LBI-38664 (PCMS)

EDACS sites interfaced to the CEC/IMC Digital Audio Switch through an Audio Board do not require the 2175 Hz tone keying signalling sequence as described on pages 16 and 17 of this manual. This is also true for all other external equipment (for example – consoles, logging recorders, the CIA rack, etc.) interfaced to the CEC/IMC via an Audio Board. EDACS sites only require a very short 2175 Hz Secure tone burst followed by a 2175 Hz hold tone to keep the site's transmitter keyed. Therefore, specifications for this circuitry on the Audio Board have been relaxed. Note the following changes to the manual (pages 16 and 17):

- duration of the 2175 Hz Secure tone burst has been reduced from 125 milliseconds ( $\pm 10\%$ ) to greater than 80 milliseconds
- presence of the function tone is *no longer guaranteed*

### ADDENDUM NO. 4 TO LBI-38664 (PCMS)

This addendum adds information on Audio Board 19D903302P3. This Audio Board replaces Audio Board 19D903302P1 in all CEC/IMC Digital Audio Switch applications. Backwards compatibility with the P1 Audio Board is retained. Also see Addendum 2 to this manual. A revised maintenance manual completely documenting the P3 Audio Board will be issued at a later date. Contact your service representative for additional information.

Audio Board 19D903302P3 information added by this addendum includes the board's:

- Assembly/Outline Diagram (pages 2 and 3)
- Schematic Diagram (pages 4 thru 15)
- Parts List (pages 16 thru 25)
- Production Changes (page 25)

#### NDTES:

1. SOLDER C174 ACROSS R145 AS SHOWN. SOLDER C274 ACROSS R245 AS SHOWN. SOLDER C374 ACROSS R345 AS SHOWN. SOLDER C474 ACROSS R445 AS SHOWN.

CONNECT JUMPER WIRE FROM U45 PIN 17 TO THE PAD OF R181, R281, R381, AND R481 AS SHOWN.

(19D903302, Sh. 2, Rev. 6B)


#### (19D903302, Sh. 2, Rev. 6B)





(19D903982, Sh. 2, Rev. 1)



¥F10 1 VEXI-

R043 4750



Vcc

Vcc

U054B

VCC

-> TDM BUS[0:7]

TDM\_BUSE 02

GÑD

(19D903982, Sh. 3, Rev. 1)

ILD\_SRC

Vcc

GND

-5V

-12V

+12V

-5V >

DX BUS[0:7] >-

U050

BI

DX\_BUSE01



(19D903982, Sh. 4, Rev. 1)



8



(19D903982, Sh. 6, Rev. 3)





(19D903982, Sh. 8, Rev. 1)



12

(19D903982, Sh. 9, Rev. 1)



(19D903982, Sh. 10, Rev. 1)





(19D903982, Sh. 12, Rev. 1)

#### AUDIO BOARD 19D903302P3, Rev. B (344A4088G1)

	(344/	02P3, Rev. B A4088G1)	C92 thru C94	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
	IS	SUE 1	C95	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
SYMBOL	PART NUMBER	DESCRIPTION	C96	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
		CAPACITORS	C97	19A705205P5	Tantalum: 6.8 μF, 10 VDCW; sim to Sprague 293D.
C1	19A703314P12	Electrolytic: 100 µF ±20%, 25 VDCW.	C101	19A705205P111	Tantalum: 47 ±10%, 10 VDCW; sim to
C2	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.	and C102		Sprague 293D.
C3	19A703314P12	Electrolytic: 100 µF ±20%, 25 VDCW.	C103	19A702052P14	Ceramic: 0.01 uE +10% 50 VDCW
C4	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.	C104	19A702052P30	Ceramic: 0.022 uE ±10% 50 VDCW
C5	19A705205P15	Tantalum: 33 µF, 16 VDCW; sim to Sprague 293D.	C106	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp
C6	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.	C107	19A702052P26	Ceramic: 0.1 µE +10% 50 VDCW
C7	19A703314P12	Electrolytic: 100 $\mu F$ ±20%, 25 VDCW.	C108	194702061P99	Ceramic: 1000 pE +5% 50 VDCW temp
C8	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.	0100	1347020011 33	coef 0 $\pm$ 30 PPM/°C.
C9	19A705205P15	Tantalum: 33 µF, 16 VDCW; sim to Sprague 293D.	C109	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C10	19A705205P12	Tantalum: .33 µF, 16 VDCW; sim to Sprague 293D.	C110	19A705205P111	I antalum: 47 ±10%, 10 VDCW; sim to Sprague 293D.
C11	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.	C111 and	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C12	19A705205P6	Tantalum: 10 µF, 16 VDCW; sim to	C112		
		Sprague 293D.	C113	19A702052P32	Ceramic: 0.22 µF ±10%, 50 VDCW.
C13	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	C114 and	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C14 and	344A4194P331250	Electrolytic: 330 µF ±20%, 25 VDCW.	C115		
C15			C116	19A705205P12	Tantalum: .33 µF, 16 VDCW; sim to
C16	19A705205P18	Tantalum: 4.7 µF ±20%, 35 VDCW.	0117	104702052026	
C17	19A705205P2	Tantalum: 1 μF, 16 VDCW; sim to	C117	194702052F20	Tontolum: 22 uE 16 VDCW: sim to
C18	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.	and C119	19A703203F12	Sprague 293D.
and C19			C120	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C20	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	C121	19A705205P18	Tantalum: 4.7 µF ±20%, 35 VDCW.
C21	19A705205P2	Tantalum: 1 µF, 16 VDCW; sim to Sprague 293D.	and C122		
C23	19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW, temp	C123	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
and C24		coef 0 ±30 PPM/°C.	C125	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C25 and	19A702061P49	Ceramic: 56 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	C131 and C132	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C26			C133	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C31	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	C134	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
and C33	19A702052P33	Ceramic: 0.1 µF ±10%, 50 VDCW.	and C135		
C34	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.	C137 thru	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C35	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	C139		
and C36			C140	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C46	19A702052P14	Ceramic: 0.01 µF ±10%. 50 VDCW.	C141	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
and C47			C143	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C49 thru	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	C144 and C145	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C65 C67	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	C146 thru C152	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C77			C161	194702052526	Ceramic: 0.1 uE +10% 50 VDCW
C79	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	0101	10/702052026	Ceramic: 0.1 uE ±10%, 50 VDCW.
thru C87			C169	194702052520	Ceramic: 0.1 µF ±10%, 50 VDCW.
C89 and	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	and C169	10/102002520	Coramic. υ. τ μι ±10 /0, 30 VDCW.
C90					

SYMBOL

PART NUMBER

DESCRIPTION

SYMBOL	PART NUMBER	DESCRIPTION
C170 and C171	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.
C172	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C173	19A702052P34	Ceramic: 0.1 µF ±10%, 25 VDCW.
C174	19A700233P1	Ceramic: 100 pF ±20%, 50 VDCW.
C175	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.
C201 and C202	19A705205P111	Tantalum: 47 ±10%, 10 VDCW; sim to Sprague 293D.
C203	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C204	19A702052P30	Ceramic: 0.022 µF ±10%, 50 VDCW.
C206	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.
C207	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C208	19A702052P105	Ceramic: 1000 pF ±5%, 50 VDCW.
C210	19A705205P111	Tantalum: 47 ±10%, 10 VDCW; sim to Sprague 293D.
C211 and C212	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C213	19A702052P32	Ceramic: 0.22 µF ±10%, 50 VDCW.
C214 and C215	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C216	19A705205P12	Tantalum: .33 μF, 16 VDCW; sim to Sprague 293D.
C217	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C218 and C219	19A705205P12	Tantalum: .33 μF, 16 VDCW; sim to Sprague 293D.
C220	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C221 and C222	19A705205P18	Tantalum: 4.7 μF ±20%, 35 VDCW.
C223	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C225	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C231 and C232	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C233	19A702052P26	Ceramic: 0.1 uE +10% 50 VDCW
C234	19A702052P14	Ceramic: $0.01 \mu E + 10\%$ 50 VDCW
and C235		
C237 thru C239	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C240	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C241	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C243	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C244 and C245	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C246 thru C252	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C261	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C263	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C268 and C269	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C270 and C271	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.

SYMBOL	PART NUMBER	DESCRIPTION
C272	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C273	19A702052P34	Ceramic: 0.1 µF ±10%, 25 VDCW.
C274	19A700233P1	Ceramic: 100 pF ±20%, 50 VDCW.
C301 and	19A705205P111	Tantalum: 47 ±10%, 10 VDCW; sim to
C302		
C303	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C304	19A702052P30	Ceramic: 0.022 µF ±10%, 50 VDCW.
C306	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.
C307	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C308	19A702052P105	Ceramic: 1000 pF ±5%, 50 VDCW.
C310	19A705205P111	Tantalum: 47 ±10%, 10 VDCW; sim to Sprague 293D.
C311 and	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C312		
C313	19A702052P32	Ceramic: 0.22 µF ±10%, 50 VDCW.
C314	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C315		
C316	19A705205P12	Tantalum: .33 µF, 16 VDCW; sim to Sprague 293D.
C317	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C318 and C319	19A705205P12	Tantalum: .33 μF, 16 VDCW; sim to Sprague 293D.
C320	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C321 and C322	19A705205P18	Tantalum: 4.7 µF ±20%, 35 VDCW.
C323	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C325	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C331 and C332	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C333	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C334	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
and C335		
C337	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
thru C339		
C340	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C341	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C343	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C344 and C345	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C346 thru C352	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C361	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C363	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C368 and C369	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C370 and C371	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.
C372	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.
C373	19A702052P34	Ceramic: 0.1 µF ±10%, 25 VDCW.
C374	19A700233P1	Ceramic: 100 pF ±20%, 50 VDCW.

SYMBOL	PART NUMBER	DESCRIPTION		SYMBOL	PART NUMBER	DESCRIPTION
C401 and	19A705205P111	Tantalum: 47 ±10%, 10 VDCW; sim to Sprague 293D.		D11	19A703595P9	Optoelectric: Green LED; sim to HLMP- 1540-010
C402 C403	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.		D12 thru	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C404	19A702052P30	Ceramic: 0.022 µF ±10%, 50 VDCW.		D19		
C406	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.		D21	T324ADP1041	Silicon: Rectifier; sim to 1N4004.
C407	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		D22 and	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C408	19A702052P105	Ceramic: 1000 pF ±5%, 50 VDCW.		D23		
C410	19A705205P111	Tantalum: 47 ±10%, 10 VDCW; sim to Sprague 293D.		D24 and D25	T324ADP1041	Silicon: Rectifier; sim to 1N4004.
C411 and	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		D32	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C412				D34	19A703595P9	Optoelectric: Green LED; sim to HLMP- 1540-010
C413	19A702052P32	Ceramic: 0.22 µF ±10%, 50 VDCW.		D35	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C414 and	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		D101	19A700083P101	Silicon: 4.7 Volt Zener: sim to BZX84-
C415				and D102		C4V7.
C416	19A705205P12	Tantalum: .33 µF, 16 VDCW; sim to Sprague 293D.		D102	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C417	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		D201	19A700083P101	Silicon: 4.7 Volt Zener; sim to BZX84-
C418	19A705205P12	Tantalum: .33 µF, 16 VDCW; sim to		and D202		C4V7.
C419		Sprague 233D.		D203	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C420	19A702052P26	Ceramic: 0.1 $\mu F$ ±10%, 50 VDCW.		D301	19A700083P101	Silicon: 4.7 Volt Zener; sim to BZX84-
C421 and	19A705205P18	Tantalum: 4.7 µF ±20%, 35 VDCW.		D302		6407.
C422				D303	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C423	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		D401 and	19A700083P101	Silicon: 4.7 Volt Zener; sim to BZX84- C4V7
C425	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		D402		
C431 and C432	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.		D403	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
C433	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		F1	404424004020	Contriduce: 2.0 Among Claus Actions sim to
C434 and	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.		ΓI	19A134901F20	Littelfuse 218 002.
C435				F2	19A134961P15	Cartridge: 1.0 Amp Slow-Action; sim to Littelfuse 218 001.
C437 thru C439	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		F3	19A134961P10	Cartridge: 0.5 Amp Slow-Action; sim to Littelfuse 218.500.
C440	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.		F101 thru	344A4252P3	Surface mount: 0.375 A, 32 V; sim to Avx Kyoera F1206A0-R37FWTR.
C441	19A702052P26	Ceramic: 0.1 $\mu F$ ±10%, 50 VDCW.		F104		
C443	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.		F201 thru	344A4252P3	Surface mount: 0.375 A, 32 V; sim to Avx Kvoera F1206A0-R37FWTR.
C444	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		F204		,
C446	194702052P14	Ceramic: 0.01 uE +10% 50 VDCW		F301 thru F304	344A4252P3	Surface mount: 0.375 A, 32 V; sim to Avx Kyoera F1206A0-R37FWTR.
thru C452				F401 thru	344A4252P3	Surface mount: 0.375 A, 32 V; sim to Avx Kyoera F1206A0-R37FWTR.
C461	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		F404		
C463	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.				JACKS
C468 and C469	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		J1 and J2	19B801587P13	DIN plug: 96-Position; sim to AMP 2- 534068-8.
C470 and C471	19A702052P1	Ceramic: 220 pF ±10%, 50 VDCW.		J3	19B209727P37	Connector: 9 contacts, sim to AMP 745781-4.
C472	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW.		J4	19B802174P2	DIN receptacle: 40-Position; sim to AMP 5-175474-5.
C473	19A702052P34	Ceramic: 0.1 µF ±10%, 25 VDCW.	ļ			RELAYS
C474	19A700233P1	Ceramic: 100 pF ±20%, 50 VDCW.		K404	40000500404	Deads & Farm O statistics in the OLOT
		DIODES		K1U1	198235621P1	Reed: 2 Form C contacts; sim to GI Clare HGZM2-C05.
D1 thru D9	19A703595P9	Optoelectric: Green LED; sim to HLMP- 1540-010		K201	19B235621P1	Reed: 2 Form C contacts; sim to GI Clare HGZM2-C05.

SYMBOL	PART NUMBER	DESCRIPTION
K301	19B235621P1	Reed: 2 Form C contacts; sim to GI Clare HGZM2-C05.
K401	19B235621P1	Reed: 2 Form C contacts; sim to GI Clare HGZM2-C05.
		INDUCTORS
L1	19A149806P2	High-current: 100 uH; sim to Dale IHA-102.
		TRANSISTORS
Q4	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q8 and Q9	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q12	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q101	19A702524P3	Silicon, N-type FET: sim to MMBFJ310.
Q103	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q201	19A702524P3	Silicon, N-type FET: sim to MMBFJ310.
Q203	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q301	19A702524P3	Silicon, N-type FET: sim to MMBFJ310.
Q303	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q401	19A702524P3	Silicon, N-type FET: sim to MMBFJ310.
Q403	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
		RESISTORS
R1	19B800607P471	Metal film: 470 ohms ±5%, 1/8 w.
R2 and	19B800607P182	Metal film: 1.8K ohms ±5%, 1/8 w.
R4	19B800607P471	Metal film: 470 ohms ±5%, 1/8 w.
R5 thru	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R10	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R11 and	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R12	400000000000000000000000000000000000000	
R13	19B800607P273	Metal film: 27K onms ±5%, 1/8 w.
R14	19B800607P471	Metal film: 4/0 onms ±5%, 1/8 W.
R15	19A702931P301	Metal film: 10K onms $\pm 1\%$ , 1/8 W.
R17	1947029312170	Metal film: $10K$ obms $\pm 1\%$ , $1/8$ W.
thru R26	19A702931P301	Nietai nim: TOK onms ±1%, 1/8 w.
R27	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R28	19B800607P471	Metal film: 470 ohms ±5%, 1/8 w.
R29	19B800607P273	Metal film: 27K ohms ±5%, 1/8 w.
R30 thru R33	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R35 thru R37	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R38	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R39	19B800607P1	Metal film: Jumper.
R41 and R42	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R43	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.

SYMBOL	PART NUMBER	DESCRIPTION
R44	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R45	19A702931P371	Metal film: 53.6K ohms ±1%, 1/8 w.
R46	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
thru R48		
R49	19B800607P471	Metal film: 470 ohms ±5%, 1/8 w.
thru R52		
R53	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R54	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R55	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R56	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R57		
R58	19B800607P471	Metal film: 470 ohms ±5%, 1/8 w.
R59	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R60	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R61 thru	19B800607P122	Metal film: 1.2K ohms ±5%, 1/8 w.
R68		
R69 thru	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R72		
R73 and	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R74		
R75 thru	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R82		
R84 thru	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R89		
R91	19B800607P332	Metal film: 3.3K ohms ±5%, 1/8 w.
R94 thru	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R96		
R98	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R101	19A702931P176	Metal film: 604 ohms $\pm 1\%$ , 1/8 w.
and R102	19A702931P301	Metal film: 10K onms $\pm 1\%$ , 1/8 W.
R104	19A702931P374	Metal film: 57.6K ohms ±1%, 1/8 w.
R105	19A702931P385	Metal film: 75K ohms ±1%, 1/8 w.
R106	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R107	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R108	19B800607P563	Metal film: 56K ohms ±5%, 1/8 w.
R109	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
R110	19B800607P333	Metal film: 33K ohms ±5%, 1/8 w.
R111	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R112	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R113	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R114	19A702931P320	Metal film: 15.8K ohms ±1%, 1/8 w.
R115	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R116	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R117	19B800607P225	Metal film: 2.2M ohms ±5%, 1/8 w.
R118	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R119	19A702931P289	Metal film: 8250 ohms ±1%, 1/8 w.
R120	198800607P563	Motal film: 56K onms ±5%, 1/8 w.
R121	19A702931P301	Motol film: 4750 chmo +1%, 1/8 W.
1/122	13/1023317200	wotar 11111. 4730 011115 ±170, 1/0 ₩.

SYMBOL	PART NUMBER	DESCRIPTION	]	SYMBOL	PART NUMBER	DESCRIPTION
R123	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R202	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R124	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.		and R203		
R125	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R204	19A702931P374	Metal film: 57.6K ohms ±1%, 1/8 w.
and R126				R205	19A702931P385	Metal film: 75K ohms ±1%, 1/8 w.
R127	19A702931P401	Metal film: 100K ohms ±1%. 1/8 w.		R206	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R128	19A702931P353	Metal film: 34.8K ohms ±1%, 1/8 w.		R207	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R129	344A3206P3	Metal film: 12.4K ohms ±0.1%, 1/8 w.		R208	19B800607P563	Metal film: 56K ohms ±5%, 1/8 w.
R130	344A3206P4	Metal film: 11.0K ohms ±0.1%, 1/8 w.		R209	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
R131	19A702931P320	Metal film: 15.8K ohms ±1%, 1/8 w.		R210	19B800607P333	Metal film: 33K ohms ±5%, 1/8 w.
R132	19A702931P360	Metal film: 41.2K ohms ±1%, 1/8 w.		R211	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
and R133				R212	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R134	19A702931P311	Metal film: 12 7K ohms +1% 1/8 w		R213	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R135	19A702931P457	Metal film: 383K obms +1% 1/8 w		R214	19A702931P320	Metal film: 15.8K ohms ±1%. 1/8 w.
R136	19A702931P468	Metal film: 499K ohms +1%, 1/8 w		R215	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R137	19A702931P403	Motal film: 105K ohms ±1%, 1/8 w		R216	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R138	194702931P3/8	Metal film: 30 9K ohms ±1%, 1/8 w		R217	19B800607P225	Metal film: 2 2M ohms ±5% 1/8 w
P120	10A702031P385	Motal film: 7500 obms ±1%, 1/8 w		R218	19A702931P401	Metal film: 100K obms +1% 1/8 w
R140	194702931P340	Metal film: 25.5K obms +1%, 1/8 w		R219	19A702931P289	Metal film: 8250 ohms +1% 1/8 w
P141	1047020318303	Motal film: 00.0K ohms ±1%, 1/8 w		R220	19B800607P563	Metal film: 56K ohms +5% 1/8 w
R141	19A702931P393	Metal film: 604 obms ±1%, 1/8 w		R221	19A702931P301	Metal film: 10K ohms +1% 1/8 w
R142	19870293TF170	Motal film: 1K obms $\pm 5\%$ 1/8 w		R222	19A702931P266	Metal film: 4750 ohms +1% 1/8 w
R 143	19B800007F102	Metal film: 10K obms $\pm 1\%$ , 1/8 w		R223	19A702931P301	Metal film: 10K ohms +1% 1/8 w
R144	104702031P426	Metal film: 222K abma : 19( - 1/9 ).		R224	19B800607P102	Metal film: 1K obms +5% 1/8 w
R 140	19A702931P436	Metal film: 232K onms ±1%, 1/8 w.		R225	196702931P301	Metal film: 10K obms +1% 1/8 w
R 140	19A702931P409	Metal film: 121K onms ±1%, 1/8 w.		and	1347023311 301	inclarmin. Tory on the 170, 170 w.
thru	1947029319301	Metal him: Tok onms $\pm 1\%$ , 1/8 w.		R220	1017000040404	
R150				R227	19A702931P401	Metal film: 100K onms $\pm 1\%$ , 1/8 w.
R151 *	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.		R228	19A702931P353	Metal film: 34.8K onms $\pm 1\%$ , 1/8 W.
R152	19A702931P266	Metal film: $4750 \text{ ohms } \pm 1\%$ , $1/8 \text{ w.}$		R229	344A3206P3	Metal film: 12.4K onms ±0.1%, 1/8 w.
R153	19A702931P301	Metal film: 10K ohms $\pm$ 1%, 1/8 w.		R230	344A3206P4	Metal film: 11.0K onms ±0.1%, 1/8 w.
R154 thru	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.		R231	19A702931P320	Metal film: 15.8K on $ms \pm 1\%$ , 1/8 w.
R161				and	19A702931P360	Metal film: $41.2$ K onms $\pm 1\%$ , 1/8 w.
R162 and	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R233		
R163				R234	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.
R164	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.		R235	19A702931P457	Metal film: $383$ K ohms $\pm 1\%$ , $1/8$ w.
R166	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.		R236	19A702931P468	Metal film: 499K ohms ±1%, 1/8 w.
R167	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.		R237	19A702931P403	Metal film: 105K ohms ±1%, 1/8 w.
R168 and	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R238	19A702931P348	Metal film: 30.9K ohms ±1%, 1/8 w.
R169				R239	19A702931P285	Metal film: 7500 ohms ±1%, 1/8 w.
R170	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.		R240	19A702931P340	Metal film: 25.5K ohms ±1%, 1/8 w.
R171				R241	19A702931P393	Metal film: 90.9K ohms ±1%, 1/8 w.
R172	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R242	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R173	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.		R243	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R174	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R244	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
and R175				R245	19A702931P436	Metal film: 232K ohms ±1%, 1/8 w.
R176	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.		R246	19A702931P409	Metal film: 121K ohms ±1%, 1/8 w.
R178	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R247 thru	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
thru R180				R251		
R182	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R252	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.
R201	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.		R253	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.

SYMBOL	PART NUMBER	DESCRIPTION
R254 thru R261	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.
R262 and R263	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R264	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R266	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
R267	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.
R268 and R269	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R270 and R271	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R272	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R273	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.
R274 and R275	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R276	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R278 thru R280	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R282	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R301	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R302 and R303	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R304	19A702931P374	Metal film: 57.6K ohms ±1%, 1/8 w.
R305	19A702931P385	Metal film: 75K ohms ±1%, 1/8 w.
R306	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R307	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R308	19B800607P563	Metal film: 56K ohms ±5%, 1/8 w.
R309	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
R310	19B800607P333	Metal film: 33K ohms ±5%, 1/8 w.
R311	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R312	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R313	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R314	19A702931P320	Metal film: 15.8K ohms ±1%, 1/8 w.
R315	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R316	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R317	19B800607P225	Metal film: 2.2M ohms ±5%, 1/8 w.
R318	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R319	19A702931P289	Metal film: 8250 ohms ±1%, 1/8 w.
R320	19B800607P563	Metal film: 56K ohms ±5%, 1/8 w.
R321	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R322	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.
R323	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R325 and R326	198800607P102	мецаі пііті: 1к onms ±5%, 1/8 w. Metal film: 10K ohms ±1%, 1/8 w.
R327	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R328	19A702931P353	Metal film: 34.8K ohms ±1%, 1/8 w.
R329	344A3206P3	Metal film: 12.4K ohms ±0.1%, 1/8 w.
R330	344A3206P4	Metal film: 11.0K ohms ±0.1%, 1/8 w.
R331	19A702931P320	Metal film: 15.8K ohms ±1%, 1/8 w.

SYMBOL	PART NUMBER	DESCRIPTION
R332 and R333	19A702931P360	Metal film: 41.2K ohms ±1%, 1/8 w.
R334	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.
R335	19A702931P457	Metal film: 383K ohms ±1%, 1/8 w.
R336	19A702931P468	Metal film: 499K ohms ±1%, 1/8 w.
R337	19A702931P403	Metal film: 105K ohms ±1%, 1/8 w.
R338	19A702931P348	Metal film: 30.9K ohms ±1%, 1/8 w.
R339	19A702931P285	Metal film: 7500 ohms ±1%, 1/8 w.
R340	19A702931P340	Metal film: 25.5K ohms ±1%, 1/8 w.
R341	19A702931P393	Metal film: 90.9K ohms ±1%, 1/8 w.
R342	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R343	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R344	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R345	19A702931P436	Metal film: 232K ohms ±1%, 1/8 w.
R346	19A702931P409	Metal film: 121K ohms ±1%, 1/8 w.
R347 thru R351	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R352	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.
R353	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R354	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.
thru R361		
R362 and R363	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R364	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.
R366	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
R367	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.
R368 and R369	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R370 and R371	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R372	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R373	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.
R374 and R375	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R376	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R378	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
thru R380		
R382	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R401	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R402 and R403	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R404	19A702931P374	Metal film: 57.6K ohms ±1%. 1/8 w.
R405	19A702931P385	Metal film: 75K ohms ±1%, 1/8 w.
R406	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.
R407	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R408	19B800607P563	Metal film: 56K ohms ±5%, 1/8 w.
R409	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
R410	19B800607P333	Metal film: 33K ohms ±5%, 1/8 w.
R411	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R412	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.

SYMBOL	PART NUMBER	DESCRIPTION	]	SYMBOL	PART NUMBER	DESCRIPTION
R413	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		R473	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.
R414	19A702931P320	Metal film: 15.8K ohms ±1%, 1/8 w.		R474	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R415	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.	ļ	and R475		
R416	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.		R476	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.
R417	19B800607P225	Metal film: 2.2M ohms ±5%, 1/8 w.		R478	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R418	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.	ļ	thru R480		
R419	19A702931P289	Metal film: 8250 ohms ±1%, 1/8 w.		R482	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.
R420	19B800607P563	Metal film: 56K ohms ±5%, 1/8 w.			10, 11 0200 11 001	
R421	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.				
R422	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.		SW1	19A149955P1	DIP, rocker: 8-Position; sim to Grayhill 76PSB08S.
R423	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		SW3	19A149923P2	Pushbutton: Single-Pole Normally-Open;
R424	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.				sim to ITT Schadow KSLOV311.
R425	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.				TRANSFORMERS
and R426				T101 and	344A3106P1	Audio Frequency, 600-Ohm Coupling; sim
R427	19A702931P401	Metal film: 100K ohms ±1%, 1/8 w.		T102		
R428	19A702931P353	Metal film: 34.8K ohms ±1%, 1/8 w.		T201	344A3106P1	Audio Frequency, 600-Ohm Coupling; sim
R429	344A3206P3	Metal film: 12.4K ohms ±0.1%, 1/8 w.		T202		
R430	344A3206P4	Metal film: 11.0K ohms ±0.1%, 1/8 w.		T301	344A3106P1	Audio Frequency, 600-Ohm Coupling; sim
R431	19A702931P320	Metal film: 15.8K ohms ±1%, 1/8 w.		T302		to Midcom 671-8000.
R432	19A702931P360	Metal film: 41.2K ohms ±1%, 1/8 w.		T401	344A3106P1	Audio Frequency, 600-Ohm Coupling; sim
and R433				and T402		to Midcom 671-8000.
R434	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.				TEST POINTS
R435	19A702931P457	Metal film: 383K ohms ±1%, 1/8 w.		TP1	344A3367P1	Metal loop w/orange insulator.
R436	19A702931P468	Metal film: 499K ohms ±1%, 1/8 w.				INTEGRATED CIRCUITS
R437	19A702931P403	Metal film: 105K ohms ±1%, 1/8 w.		111	10013471702	Linear: 12 Volt Regulator: sim to
R438	19A702931P348	Metal film: 30.9K ohms ±1%, 1/8 w.	ļ	01	13/13/17/2	MC7812CT.
R439	19A702931P285	Metal film: 7500 ohms ±1%, 1/8 w.		U2	19A134718P2	Linear: -12 Volt Regulator; sim to
R440	19A702931P340	Metal film: 25.5K ohms ±1%, 1/8 w.	ļ	113	19A134718P1	Linear: -5 Volt Regulator: sim to uA79051
R441	19A702931P393	Metal film: 90.9K ohms ±1%, 1/8 w.		U4	19A703483P311	Digital: Quad 2-Input OR Gate: sim to
R442	19A702931P176	Metal film: 604 ohms ±1%, 1/8 w.				74HC32.
R443	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.	ļ	U5	19A134717P1	Linear: 5 Volt Regulator; sim to
R444	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		U31	19A705828P1	Microcomputer: sim to Siemens
R445	19A702931P436	Metal film: 232K ohms ±1%, 1/8 w.				SAB80C535.
R446	19A702931P409	Metal film: 121K ohms ±1%, 1/8 w.		U32	19A703987P306	Digital: Presettable Counter; sim to 74HC161.
R447 thru	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		U33	19A703483P321	Digital: Hex Schmitt Trigger Inverter; sim to
R451						74HC14.
R452	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.		U34 and	19A703471P323	Digital: Quad 2-Input Data Selector/Mux.; sim to 74HC157.
R453	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.		U35		
R454 thru	19A702931P266	Metal film: 4750 ohms ±1%, 1/8 w.		U36	19A703471P318	Digital: Octal Tri-State Transceiver/Latch; sim to 74HC573.
R461				U38	19A703471P323	Digital: Quad 2-Input Data Selector/Mux.;
R462 and	19A702931P301	Metal film: 10K ohms ±1%, 1/8 w.				sim to 74HC157.
R463				U39	19A703471P320	Digital: 3-Line To 8-Line Decoder; sim to 74HC138.
R464	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.		U40	19A703483P302	Digital: Quad 2-Input NAND Gate; sim to
R466	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.	ļ			74HC00.
R467	19A702931P311	Metal film; 12.7K ohms ±1%, 1/8 w.		U41	19A705603P5	Digital: 8K x 8-Bit Static RAM; sim to KM6264AL-10.
R468 and	19A702931P301	IVIETAI TIIM: 10K ohms ±1%, 1/8 w.		U42	19A703483P302	Digital: Quad 2-Input NAND Gate; sim to
R469	4047000010/=-	Matal Glass 00 ( 1 - 40 / 117				74HC00.
R470 and	19A702931P176	ועופנמו זווm: 604 0hms ±1%, 1/8 w.		U43	19A703483P319	Digital: 4-Bit Magnitude Comparator; sim to 74HC85.
K4/1	4047000210001	Matal films 40K aluma - 40K 4/0 ····		U44	19A704380P302	Digital: Dual Data Flip-Flop; sim to
11412	13/10/23311301	wietai IIIII. TUK UIIIIS ±170, 1/0 W.	L			14HU14.

SYMBOL	PART NUMBER	DESCRIPTION
U45	19A149956P1	Digital: Serial Communication Controller; sim to 82525N.
U46	344A4826G1	Digital: PAL; sim to TICPAL22V10Z- 25C.(Programmed.)
U47 thru U49	19A703471P318	Digital: Octal Tri-State Transceiver/Latch; sim to 74HC573.
U50 and U51	19A149953P202	Digital: 4-Channel Bus Transceiver; sim to DS3897.
U53	344A3559G2	Digital: PAL; sim to TICPAL22V10Z- 25C.(Programmed.)
U54	19A704380P302	Digital: Dual Data Flip-Flop; sim to 74HC74.
U55	19A705180P102	Digitally Controlled Pot: 40 - 10K ohms; sim to X9103S.
U56	19A149953P201	Digital: 8-Channel Bus Transceiver; sim to DS3896.
U57	344A3064P205	Digital: Quad 2-Input Multiplexer; sim to 74HCT157.
U59	19A704380P315	Digital: Octal 3-State Inverting Flip-Flop; sim to 74HC564.
U60	19A703483P101	Digital: Quad 2-Input NOR Gate; sim to 74HC02.
U61	19A703471P308	Digital: Octal Bus Transceiver; sim to 74HC245.
U62	344A3122P1	Linear: PCM filter; sim to National TP3040.
U63 and U64	19A704380P321	Digital: Monostable Multivibrator; sim to 74HC123.
U65	19A703483P308	Digital: Dual 4-Input NAND Gate; sim to 74HC20.
U66	19A703483P311	Digital: Quad 2-Input OR Gate; sim to 74HC32.
U67	19A704380P310	Digital: Quad Data Flip-Flop w/Clear; sim to 74HC175.
U68	344A3071P1	Linear: Quad Optocoupler; sim to Siemens ILQ66-004T.
U69	19A703987P322	Digital: 8-Bit Shift Register; sim to 74HC165.
U70	344A3557G3	Digital: PAL; sim to TICPAL22V10Z- 25C.(Programmed.)
U71	344A3071P1	Linear: Quad Optocoupler; sim to Siemens ILQ66-004T.
U72	19A703471P305	Digital: Quad 3-State Buffer; sim to 74HC126.
U73	344A3039P201	Digital: Driver/Receiver, EIA-232D/V.28; sim to MC145406.
U83	19A703483P305	Digital: Quad 2-Input AND Gate; sim to 74HC08.
U89	19A703483P320	Digital: Dual 4-Input AND Gate; sim to 74HC21.
U90	19A704380P302	Digital: Dual Data Flip-Flop; sim to 74HC74.
U91	RYTUA113001/C	Digital: Micro Supervisor; sim to MAX690A.
U94	344A3558G2	Digital: PAL; sim to TICPAL22V10Z- 25C.(Programmed.)
U101	19A703987P322	Digital: 8-Bit Shift Register; sim to 74HC165.
U102	344A3560G2	Digital: PAL; sim to TICPAL22V10Z- 25C.(Programmed.)
U103	344A3105P1	Digital: PCM CODEC & Filter; sim to TP3076A.
U104	19A704380P302	Digital: Dual Data Flip-Flop; sim to 74HC74.

SYMBOL	PART NUMBER	DESCRIPTION
U105	19A703483P302	Digital: Quad 2-Input NAND Gate; sim to 74HC00.
U106	344A3123P1	D/A converter: 14-bit; sim to Analog Devices AD7840.
U107	19A705180P102	Digitally Controlled Pot: 40 - 10K ohms; sim to X9103S.
U108	344A3122P1	Linear: PCM filter; sim to National TP3040.
U109	344A3124P1	Linear: Switched capacitor filter; sim to National MF5.
U110	19A703483P305	Digital: Quad 2-Input AND Gate; sim to 74HC08.
U111	19A704883P2	Digital: Quad Op Amp; sim to MC3303D.
U112	344A3113P101	Analog: Quad SPDT Switch; sim to MAX333.
U113	19A704380P321	Digital: Monostable Multivibrator; sim to 74HC123.
U114	19A702705P4	Digital: Quad Analog Switch/Multiplexer; sim to 4066BM.
U115	344A3070P3	Digital: Quad JFET-Input Op Amp; sim to TL074.
U116	344A3129P2	Digital: Logic Cell Array; sim to XC3030- 70.
U117	344A3561G9 *	Digital: Serial PROM; sim to XC1736A. (Programmed.)
U118	344A3562G3	Digital: 2K x 8-Bit EPROM; sim to CY7C291-35 or TMS27C291-35. (Programmed.)
U119	344A3563G3	Digital: 2K x 8-Bit EPROM; sim to CY7C291-35 or TMS27C291- 35.(Programmed.)
U120	19A702934P4	Digital: 2K x 8-bit RAM; sim to Toshiba TC5517AFL.
U121	344A3112P1	Digital: Multiplier Accumulator; sim to Cypress CY7C510-55.
U122	344A3129P1	Digital: Logic Cell Array; sim to XC3020- 70.
U123	19A704380P302	Digital: Dual Data Flip-Flop; sim to 74HC74.
U201	19A703987P322	Digital: 8-Bit Shift Register; sim to 74HC165.
U202	344A3560G2	Digital: PAL; sim to TICPAL22V10Z-25C. (Programmed.)
U203	344A3105P1	Digital: PCM CODEC & Filter; sim to TP3076A.
U204	19A704380P302	Digital: Dual Data Flip-Flop; sim to 74HC74.
U205	19A703483P302	Digital: Quad 2-Input NAND Gate; sim to 74HC00.
U206	344A3123P1	D/A converter: 14-bit; sim to Analog Devices AD7840.
U207	19A705180P102	Digitally Controlled Pot: 40 - 10K ohms; sim to X9103S.
U208	344A3122P1	Linear: PCM filter; sim to National TP3040.
U209	344A3124P1	Linear: Switched capacitor filter; sim to National MF5.
U210	19A703483P305	Digital: Quad 2-Input AND Gate; sim to 74HC08.
U211	19A704883P2	Digital: Quad Op Amp; sim to MC3303D.
U212	344A3113P101	Analog: Quad SPDT Switch; sim to MAX333.
U213	19A704380P321	Digital: Monostable Multivibrator; sim to 74HC123.
U214	19A702705P4	Digital: Quad Analog Switch/Multiplexer; sim to 4066BM.

SYMBOL	PART NUMBER	DESCRIPTION	]	SYMBOL	PART NUMBER	DESCRIPTION
U215	344A3070P3	Digital: Quad JFET-Input Op Amp; sim to TL074.		U403	344A3105P1	Digital: PCM CODEC & Filter; sim to TP3076A.
U216	344A3129P2	Digital: Logic Cell Array; sim to XC3030- 70.		U404	19A704380P302	Digital: Dual Data Flip-Flop; sim to 74HC74.
U217	344A3561G8 *	Digital: Serial PROM; sim to XC1736A. (Programmed.)		U405	19A703483P302	Digital: Quad 2-Input NAND Gate; sim to 74HC00.
U218	344A3562G3	Digital: 2K x 8-Bit EPROM; sim to CY7C291-35 or TMS27C291-35.		U406	344A3123P1	D/A converter: 14-bit; sim to Analog Devices AD7840.
U219	344A3563G3	(Programmed.) Digital: 2K x 8-Bit EPROM; sim to		U407	19A705180P102	Digitally Controlled Pot: 40 - 10K ohms; sim to X9103S.
		CY7C291-35 or TMS27C291-35. (Programmed.)		U408	344A3122P1	Linear: PCM filter; sim to National TP3040.
U220	19A702934P4	Digital: 2K x 8-bit RAM; sim to Toshiba TC5517AFL.		U409	344A3124P1	Linear: Switched capacitor filter; sim to National MF5.
U221	344A3112P1	Digital: Multiplier Accumulator; sim to Cypress CY7C510-55.		U410	19A703483P305	Digital: Quad 2-Input AND Gate; sim to 74HC08.
U222	344A3129P1	Digital: Logic Cell Array; sim to XC3020-		U411	19A704883P2	Digital: Quad Op Amp; sim to MC3303D.
U301	19A703987P322	Digital: 8-Bit Shift Register; sim to		U412	344A3113P101	Analog: Quad SPDT Switch; sim to MAX333.
U302	344A3560G2	Digital: PAL; sim to TICPAL22V10Z-25C.		U413	19A704380P321	Digital: Monostable Multivibrator; sim to 74HC123.
U303	344A3105P1	Digital: PCM CODEC & Filter; sim to		U414	19A702705P4	Digital: Quad Analog Switch/Multiplexer; sim to 4066BM.
U304	19A704380P302	Digital: Dual Data Flip-Flop; sim to		U415	344A3070P3	Digital: Quad JFET-Input Op Amp; sim to TL074.
U305	19A703483P302	74HC74. Digital: Quad 2-Input NAND Gate; sim to		U416	344A3129P2	Digital: Logic Cell Array; sim to XC3030- 70.
U306	344A3123P1	74HC00. D/A converter: 14-bit; sim to Analog		U417	344A3561G8 *	Digital: Serial PROM; sim to XC1736A. (Programmed.)
U307	19A705180P102	Devices AD7840. Digitally Controlled Pot: 40 - 10K ohms; sim to X9103S.		U418	344A3562G3	Digital: 2K x 8-Bit EPROM; sim to CY7C291-35 or TMS27C291-35. (Programmed.)
U308	344A3122P1	Linear: PCM filter; sim to National TP3040.		U419	344A3563G3	Digital: 2K x 8-Bit EPROM; sim to
U309	344A3124P1	Linear: Switched capacitor filter; sim to National MF5.				CY7C291-35 or TMS27C291-35. (Programmed.)
U310	19A703483P305	Digital: Quad 2-Input AND Gate; sim to 74HC08.		U420	19A702934P4	Digital: 2K x 8-bit RAM; sim to Toshiba TC5517AFL.
U311	19A704883P2	Digital: Quad Op Amp; sim to MC3303D.		U421	344A3112P1	Digital: Multiplier Accumulator; sim to Cypress CY7C510-55.
U312	344A3113P101	Analog: Quad SPDT Switch; sim to MAX333.		U422	344A3129P1	Digital: Logic Cell Array; sim to XC3020- 70.
U313	19A704380P321	Digital: Monostable Multivibrator; sim to 74HC123.				FUSE SOCKETS
U314	19A702705P4	Digital: Quad Analog Switch/Multiplexer;		XF1A	19A116688P2	Clip: sim to Littelfuse 111501.
U315	344A3070P3	Digital: Quad JFET-Input Op Amp; sim to		XF1B and XF2A	19A116688P2	Clip: sim to Littelfuse 111501.
U316	344A3129P2	Digital: Logic Cell Array; sim to XC3030-		XF2B and	19A116688P2	Clip: sim to Littelfuse 111501.
U317	344A3561G8 *	Digital: Serial PROM; sim to XC1736A.		XF3A XF3B	19A116688P2	Clip: sim to Littelfuse 111501.
U318	344A3562G3	Digital: 2K x 8-Bit EPROM; sim to				SOCKETS
11319	34443563G3	(Programmed.)		XU31	344A3339P5	PLCC surface mount: 68-Pin; sim to AMP 822070-4.
0010	0+1/1000000	CY7C291-35 or TMS27C291-35. (Programmed.)		XU46	344A3339P2	PLCC surface mount: 28-Pin; sim to AMP 822066-4.
U320	19A702934P4	Digital: 2K x 8-bit RAM; sim to Toshiba TC5517AFL.		XU99	19A700156P17	DIP: 32-Pin low-profile; sim to AMP 2- 644018-3.
U321	344A3112P1	Digital: Multiplier Accumulator; sim to Cypress CY7C510-55.		XU117 XU118	19A700156P15	DIP: 8-Pin, tin plated.
U322	344A3129P1	Digital: Logic Cell Array; sim to XC3020- 70.		and XU119		2-641932-1.
U401	19A703987P322	Digital: 8-Bit Shift Register; sim to		XU217	19A700156P15	DIP: 8-Pin, tin plated.
11402	344A3560G2			XU218 and	19A700156P19	DIP: 24-positions, tin plated; sim to AMP 2-641932-1.
0702	0.117.000002	(Programmed.)		XU219		

SYMBOL	PART NUMBER	DESCRIPTION
XU317	19A700156P15	DIP: 8-Pin, tin plated.
XU318 and XU319	19A700156P19	DIP: 24-positions, tin plated; sim to AMP 2-641932-1.
XU417	19A700156P15	DIP: 8-Pin, tin plated.
XU418 and XU419	19A700156P19	DIP: 24-positions, tin plated; sim to AMP 2-641932-1.
		CRYSTALS
Y1	19A702511G15	Quartz: 11.059200 MHz.
Y2	19A702511G5	Quartz: 11.520000 MHz.
		MISCELLANEOUS
	19C852126P2	Panel, front: aluminum, lettered.
	344A4192P1	Kit, Mounting.
	N80P9005B6	Machine screw, pan head, steel, No.4- 40UNC x 5/16".
	N404P11B6	Lockwasher, internal tooth: No.4.
	7141225P2	Nut, Hex: 4-40.

#### PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter" which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for the descriptions of parts affected by these revisions.

#### Rev. A AUDIO BOARD 19D903302P3

To improve audio operation, changed PROM U117 from 344A3561G7 to 344A3561G9 and changed PROMs U217, U317 & U417 from 344A3561G6 to 344A3561G8.

#### Rev. B AUDIO BOARD 19D903302P3

To improve FPGA programming at power-up, changed R151 from 10K ohms (19B800607P103) to 1K ohms (19B800607P102).